

To Our Valued Customers

2008 marked the 50th anniversary of our company's formation as a provider of high-quality components to industry. Fifty years ago, the electronics, computer and telecom industries were just passing their infancy. Cellular phones, PC's and most other of today's sophisticated products had not yet been born. Through the decades, our continuing success has been the result of our commitment to two principles: maintaining a high standard of quality in all our products, and applying our expertise and imagination to expand the boundaries of technology.

As a founder of the original and patent company, I am fortunate to have been able to watch our group grow and prosper. Today, Interplex Industries, Inc., is the parent of 30 subsidiary companies throughout the world. Global manufacturing facilities are located throughout the U.S., Europe, the Mideast, India, Singapore and China, with expansion planned for other areas. And today, Interplex is the world's leading supplier of many types of leads, as well as stamped and insert molded products for the global electronics, computer, automotive, avionics and telecom industries.

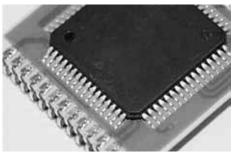
Our leadership is augmented by the technology, resources and market expertise available throughout our interrelationships with our sister companies throughout the world. We intend to maintain and enhance this leadership and increase market share for ourselves and you, our customer, by continuing to supply continuously improved state-of-the-art products.

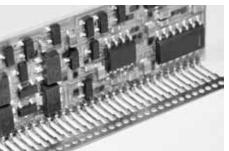
Jack Seidler

Chairman Interplex Industries, Inc.

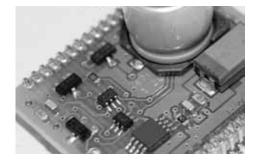
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Revolutionary Connections with Interplex Solder & Flux Bearing Leads

Our company has been in the business of manufacturing stamped parts since 1958. In the early 1970's, we began producing various types of nonsolder and solder-clad circuit leads. As circuitry proliferated in more and more applications, it became apparent that there was a need for a better lead - one that soldered more consistently, produced fewer rejects, and offered a substantially higher degree of uniformity.

In response to this need, Interplex NAS introduced its revolutionary solder and flux bearing leads (SBL) to the worldwide electronics industry in the late 1970's. Though there have been continuous modifications and improvements in solder and flux bearing leads since their introduction, the basic requirements have not changed. Industry continues to need leads that solder with a consistency close to 100% and contain a precise predetermined amount of solder and flux. The amount must be adequate for good electrical and mechanical bonding, but not so much as to create shorting of bridging situations.

Today, the advantages of Interplex NAS solder and flux bearing leads are recognized around the world. Over the years Interplex has produced many billions of leads for thousands of different customers and applications. And today, Interplex NAS constantly develops new products to meet the increasing demands of industry, particularly when it comes to finer lead pitches.

Making revolutionary connections with solder

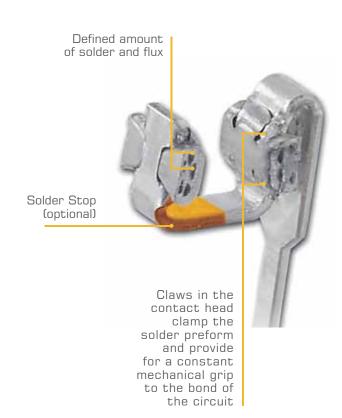
Year by year, electronic circuitry seems almost to double in power and sophistications. Yet, the process of soldering leads to circuits and connectors remained remarkably low-tech... until Interplex introduced the revolutionary solder and flux bearing lead.

In one brainstorm, Interplex turned painstaking, unreliable hand-soldering or solder-dipping into simple, one-step process that virtually eliminates the problem of rejects.

Over the years, Interplex has applied its proprietary solder and flux bearing interconnects to the latest generation of components for both surface mount and "through-hole" technologies in applications ranging from consumer products to high-reliability automotive components - saving its clients countless millions in process costs, and earning over 50 patent awards along the way.

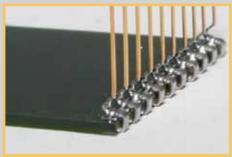
Solder Stop

A solder stop can be provided to prevent solder wicking and to properly direct the solder flow to achieve high quality solder joints. The solder stop and its location is optional dependent on the specific application.













Interplex NAS engineers developed the breakthrough concept of including, mechanically attached to each lead clip, a slug containing a precise amount of solder and flux that can be easily reflowed and directed to the conductor pad. This unique solution for attaching leads to hybrid and PCB circuits offers a world of advantages ... just to mention some of them...

One-Step Assembly

The Interplex NAS lead can be simply pushed onto a substrate and reflowed by any method – with no intermediate operations required. This simple, one-step method of assembly and reflow is the key to substantially reducing process costs.

Consistent high quality

Interplex NAS leads bear a uniform solder slug with a core of flux, which creates a perfect mechanical and electrical bond every time.

100% solderability

The unique design of Interplex NAS "claw" type leads guarantees direct contact between the solder and the conductor pad. This makes unsoldered joints totally non-existent.

Elimination of rejects

With conventional solder paste and dipping, the chance of bridging and wicking greatly increases as pitches become smaller. Interplex NAS leads eliminate this and other problems, making costly inspection and rework a thing of the past.

ONE-STEP ASSEMBLY, HIGH QUALITY, RELIABILITY

Easy automated assembly

By use of a hot bar or other localized heating device, a simple machine can assemble a ceramic substrate or PC board to Interplex NAS leads and reflow the solder simultaneously. This means you need only one operator, one machine and one process to complete your entire pin-to-substrate assembly - with no additional process costs.

Adaptability to safe, local heating

The chances of damaging prepopulated components are greatly reduced, because Interplex NAS leads can be bonded to pads without raising the temperature of the boards to the reflow point.

Accommodates choice of solder & flux

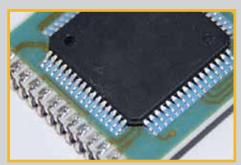
Interplex NAS leads allow greater flexibility in stacked and compound soldering operations. We can also produce leads with many different types of solder with varying melting points, and with any type of flux.

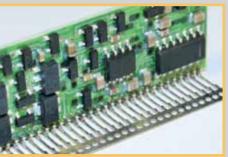
Overall significantly reduced costs

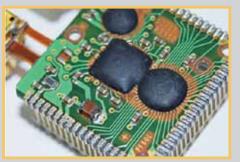
Interplex NAS solder and flux bearing leads greatly reduce process costs, resulting in a significantly less expensive finished product.

An end to thermal stress and vibration failure

The strain relief of Interplex NAS surface mount clip legs compensates for different rates of expansion between ceramic components and PCB's, and resists vibration failures.











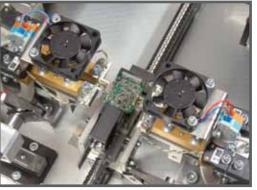


Interplex Assembly and Reflow Equipment

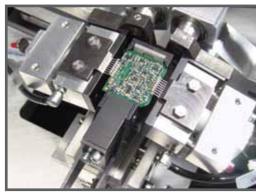
The greatest benefit of Interplex NAS lead attachment and reflow machines is that they allow the entire lead assembly process to take place in a very small space.

For example, our SIP assembly machine, taking up only approx. 1m X 2m space, can selectively knock out unwanted pins, assemble, reflow and remove the tie-bar. Other methods require three or four different machines that could take up five to ten times more space.

Interplex NAS offers a wide range of assembly equipment, from simple, inexpensive hand tools to semi- and fully automatic assembly machines, handling SIP, DIP, SMT contacts.







Tie Bar Removal Station

COMMITMENT TO QUALITY

Industry leaders worldwide rely on our commitment to Quality

Our unyielding commitment to the highest standards of quality - and our ability to continually achieve those standards - are recognized by industry-leading manufacturers around the world. These demanding customers know they can rely on us to produce design from the smallest contacts to complex mechatronic parts that meets the most challenging requirements.

Our dedication to design and manufacturing excellence is evident throughout the company. From raw materials, to manufacturing, to packaging and shipping, our quality assurance program applies statistical analysis, strict process control and other quality management systems to ensure that we always achieve the highest level of excellence.

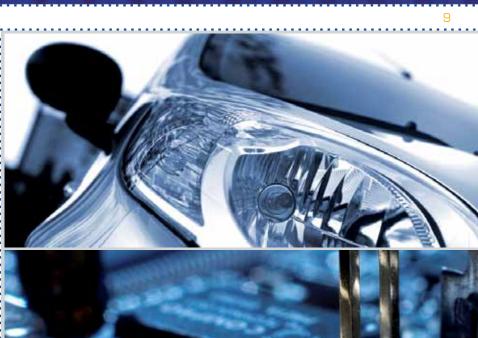
Our customers trust us to focus on the smallest details... to use our broad base of knowledge and experience to anticipate and solve potential problems - to develop innovative design and manufacturing solutions for their special product needs - and, in the end, to deliver products of uncompromising precision, quality and value.









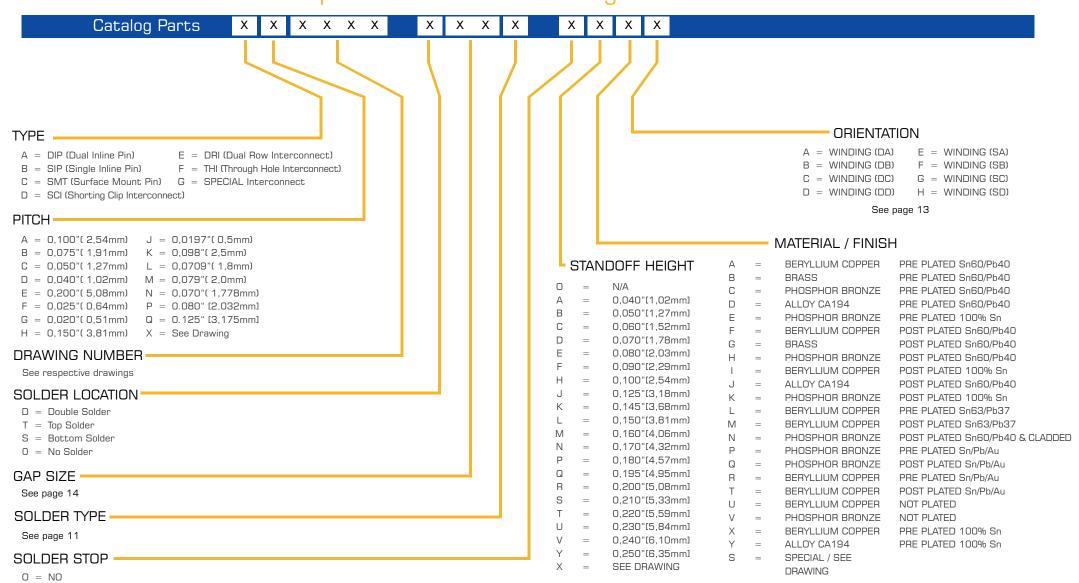




S = YES



Interplex NAS Part Numbering Code



Reflow Methods

Some of the suggested reflow methods are:

- Hot Bar
- Hot Air
- Hot Gas
- Thermode
- Laser
- Infrared
- Vapor Phase



Selective Plating Capabilities

Our unique design allows us to change efficiently from control depth plating to selective area plating without costly changeover times. We offer our costumers a variety of quality plated finishes, including gold, silver, palladium, nickel, bright nickel, tin, bright tin, tin/lead and copper.

SOLDER & FLUX TYPES

Code	Alloy		Melting Ten	nperature	
		Soldius °F	Soldius °C	Liquidus °F	Liquidus °C
0	NON-SOLDER				
А	Sn60 Pb40 Solid No Flux	361	183	370	188
В	Sn60 Pb40 Flux Type No Clean	361	183	370	188
С	Sn60 Pb40 Flux Type RMA Mild Active	361	183	370	188
E	Sn10 Pb90 SOLID NO FLUX	514	268	576	302
F	Sn10 Pb90 FLUX TYPE NO CLEAN	514	268	576	302
G	Sn10 Pb90 FLUX TYPE RMA MILD ACTIVE	514	268	576	302
1	Sn62 Pb36 Ag2 SOLID NO FLUX	354	179	354	179
J	Sn62 Pb36 Ag2 FLUX TYPE NO CLEAN	354	179	354	179
K	Sn62 Pb36 Ag2 FLUX TYPE RMA MILD ACTIVE	354	179	354	179
М	Sn96 Ag4 SOLID NO FLUX	430	221	430	221
N	Sn96 Ag4 FLUX TYPE NO CLEAN	430	221	430	221
W	Sn96 Ag4 FLUX TYPE RMA MILD ACTIVE	430	221	430	221
Q	Sn10 Pb88 Ag2 SOLID NO FLUX	514	268	576	302
R	Sn10 Pb88 Ag2 FLUX TYPE NO CLEAN	514	268	576	302
S	Sn10 Pb88 Ag2 FLUX TYPE RMA MILD ACTIVE	514	268	576	302
U	Sn63 Pb34 SOLID NO FLUX	361	183	361	183
V	Sn63 Pb34 FLUX TYPE NO CLEAN	361	183	361	183
Υ	Sn63 Pb34 FLUX TYPE RMA MILD ACTIVE	361	183	361	183
1	Sn96.5 Ag3 Cu0.5 SOLID NO FLUX	424	218	424	218
2	Sn96.5 Ag3 Cu0.5 FLUX TYPE NO CLEAN	424	218	424	218
3	Sn96.5 Ag3 Cu0.5 FLUX TYPE RMA MILD ACTIVE	424	218	424	218
	RoHS COMPLIANT				

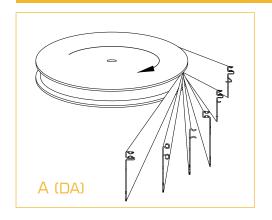


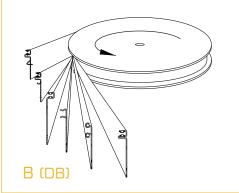


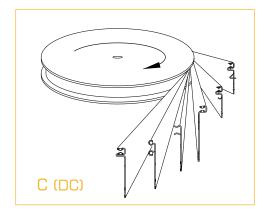
Lot Sizes

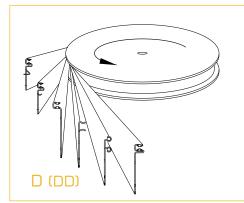
Туре	Pitch	Gap	Other	Lotsize
	.100 [2.54]	ALL		30,000
A = DIP	.075 [1.905]	ALL		30,000
	.050 [1.27]	ALL	07AA ONLY	36,000
	.050 [1.27]	ALL	21CA ONLY	50,000
		.000 [0.00]022 [0.56]		32,000
	.100 [2.54]	.023 (0.58)030 (0.77)		30,000
		.031 [0.79] - and above		24,000
B = SIP		ALL	.017 [0.43] Thick	24,000
	.075 [1.905]	ALL		36,000
	.050 [1.27]	.000 [0.00]030 [0.77]		50,000
		.031 [0.79] - and above		36,000
	.020 [0.58]	ALL		125,000
	.025 [0.64]	ALL		100,000
C = SMT	.040 [1.02]	ALL		50,000
	.050 [1.27]	ALL		50,000
	.100 [2.54]	ALL		25,000
		.000 [0.00]022 [0.56]		32,000
	.100 [2.54]	.023 (0.58)030 (0.77)		30,000
		.031 [0.79] - and above		24,000
D = SCI		ALL	.017 [0.43] Thick	24,000
	.075 [1.905]	ALL		36,000
	.050 [1.27]	.000 [0.00]030 [0.77]		50,000
		.031 [0.79] - and above		36,000
F = THI	SOLDER			36,000
	NON SOLDER			40,000
	.125 [3.175]	ALL	1457-1458 ONLY	28,000
	.100 [2.54]	NONE	NON SOLDER	100,000
SPECIAL	.100 [2.54]	NONE	SOLDER	100,000
	.075 [1.905]	NONE	SOLDER	100,000
	.050 [1.27]	NONE	SOLDER	150,000
	.050 [1.27]	ALL	07EA ONLY	50,000

DIP/SMT/SCI/THI

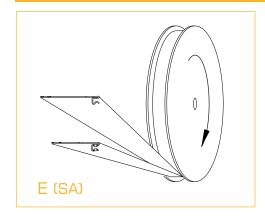


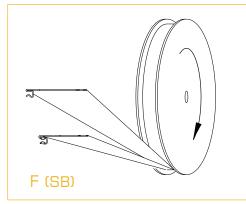


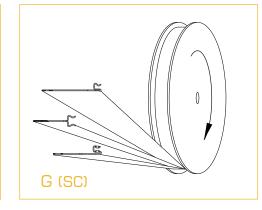


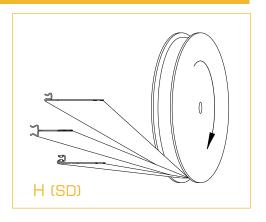


SIP







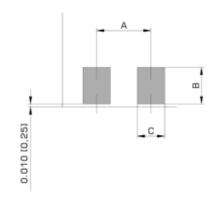




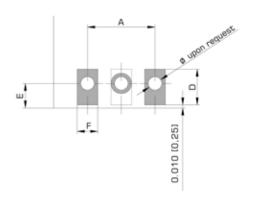
Recommended Pad Sizes

The pad sizes below are for reference only. Actual pad size may vary by the types of pin selected and the specific application.

SIP, DIP & SMT



THI (Through Hole Interconnect)



		SIP, DIP, SMT			Press Fit
A (pitch)	В	С	D	E	F
.100 [2.54]	.080 [2.03]	.060 [1.52]	.070 [1.78]	.055 [1.40]	.038 [0.97]
.075 [1.905]	.080 [2.03]	.060 [1.52]			
.050 [1.27]	.060 [1.52]	.036 [0.91]			
.040 [1.02]	.050 [1.27]	.018 [0.46]			
.025 [0.635]		.013 [0.33]			
.020 [0.508]					

Substrate Thickness / Gap Size

The clip opening or gap is indicated by "G" on our drawings. The gap on our parts is always smaller than the substrate thickness. Listed below are some of the common substrate thickness and the corresponding gaps. The actual gaps available for each part are indicated below the drawings on each page.

Subs Thick		Ga	ap	Gap code
inches ± .002	mm ± .05	inches ± .002	mm ± .05	
.005	0.13	.002	0.05	02
.015	0.38	.012	0.31	12
.022	0.56	.018	0.46	18
.025*	0.64	.022	0.56	22
.030	0.77	.026	0.66	26
.035	0.89	.032	0.81	32
.040*	1.02	.036	0.91	36
.045	1.14	.041	1.04	41
.050*	1.27	.046	1.17	46
.060*	1.52	.056	1.42	56
.064	1.63	.060	1.52	60
.080*	2.03	.072	1.83	72

*Recommended gaps. More gaps are available upon request.

MATERIAL SELECTION For Hybrid and Chip Carrier Chips

The evolution of hybrid and chip carrier technology has created the need for an effective interconnection scheme. The solution that has been developed is the edge clip. However, there is a wide variety of edge clips available today. In addition to both solder and non-solder bearing types, the designs available are as varied as the devices they can be applied to.

Also, wide range of materials are used to manufacture edge clips. All of this has led to confusion as to the best clip / material combination to use in a specific application.

The three basic factors which affect material selection are:

- 1. Mechanical
- 2. Electrical
- 3. Thermal

The types of materials commonly used are:

- 1. Coppers
- 2. Beryllium Copper
- 3. Brasses
- 4. Bronzes
- 5. Phosphor Bronze
- 6. Leadframe materials (Kovar and F42 A alloy)

Interplex NAS can provide you with a complete report that details these peel/shear tests and reviews the key factors in material selection. Please contact us for a copy.

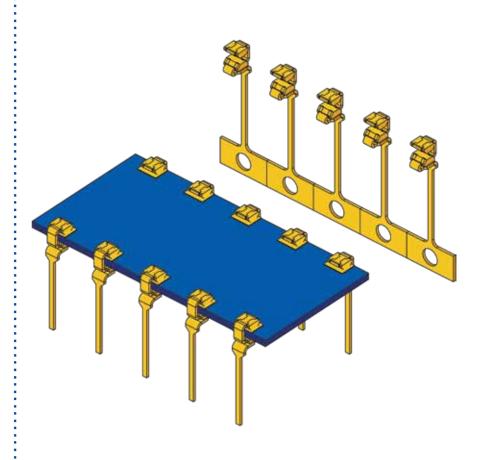






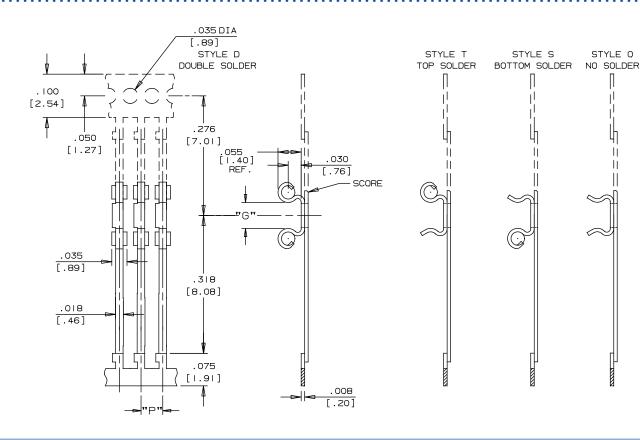
Dual Inline Package

	Di	rawing N	lo.		Pit	cch	Page
07AA					C = .050[1.27]	A = .100[2.54]	18
10AA					A = .100[2.54]		19
13BA					C = .050[1.27]		20
21CA					C = .050[1.27]		21
36AA	36CA				N = .070[1.778]		22
12BA	12BB	12BC	12BD		L = .071[1.80]		23
02AA	02BA				B = .075[1.905]		24
24BA					B = .075[1.905]	H = .150[3.81]	25
01AA					A = .100[2.54]		26
O8AA					A = .100[2.54]		27
08CA	08CB	0800	08CD		A = .100[2.54]		28
11AA					A = .100[2.54]		29
12AA	12AB				A = .100[2.54]		30
12CA	12CB	12CC	12CD		A = .100[2.54]		31
14AC					A = .100[2.54]		32
25BB	25BG	26BA			A = .100[2.54]		33
25DA	25DB	25DC	25DD	25DE	A = .100[2.54]		34
26BB					A = .100[2.54]		35
26BC					A = .100[2.54]		36
32BA	32BB				A = .100[2.54]		37





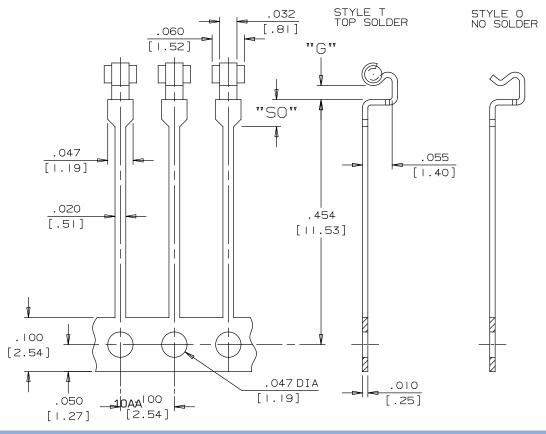
.050 [1.27]/.100 [2.54] PITCH



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Т	YPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A =	: DIP	A = .100[2.54] C = .050[1.27]	07AA	D = Double T = Top S = Bottom O = No Solder	22 = .022(0.558) 36 = .036(0.914) 56 = .056(1.42)	See Chart on Page 11	O = No Stop S = Stop	O = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = WINDING (DD)
COL	DF:									

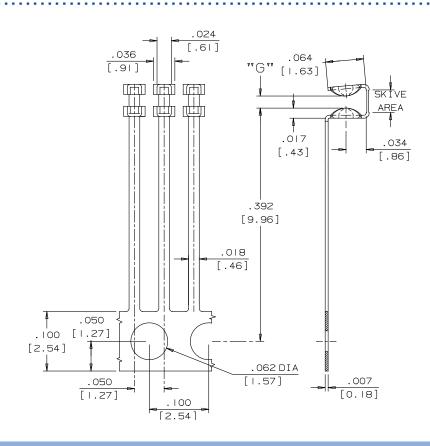
www.interplexnas.de



A = DIP	TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
	A = DIP	A = .100[2.54]	10AA		36 = .036[0.914]			B = .050[1.27]	Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze	D = Winding (DD)



.050 [1.27] PITCH

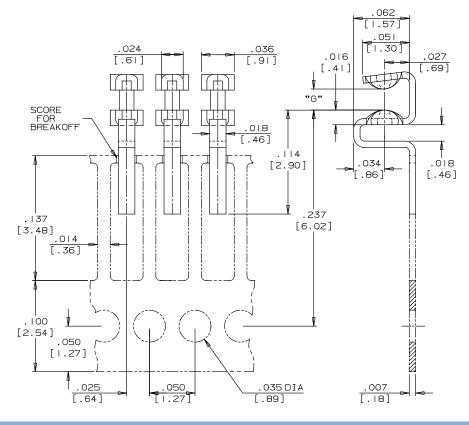


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TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	C = .050[1.27]	13BA	D = Double T = Top S = Bottom O = No Solder	22 = .022(0.558) 36 = .036(0.914) 56 = .056(1.42)	See Chart on Page 11	O = No Stop S = Stop	O = None	X = Beryllium Copper Pre- Plated 100% Sn I = Beryllium Copper Post- Plated 100% Sn A = Beryllium Copper Pre-Plated Sn60/Pb40 F = Beryllium Copper Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

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www.interplexnas.de

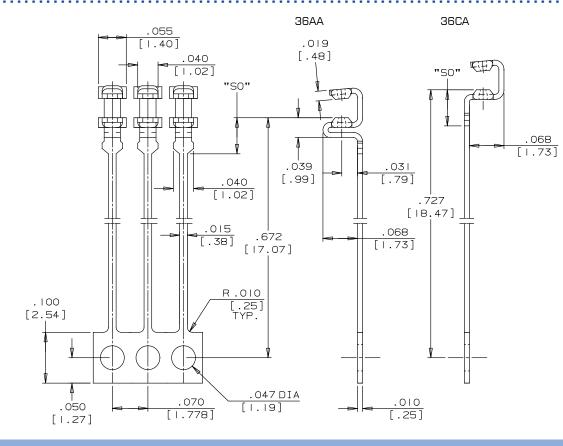


TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	C = .050[1.27]	21CA	D = Double T = Top S = Bottom O = No Solder	22 = .022(0.558) 36 = .036(0.914) 56 = .056(1.42) 72 = .072(1.83) 77 = .077(1.96)	See Chart on Page 11	O = No Stop S = Stop	O = None	X = Beryllium Copper Pre- Plated 100% Sn I = Beryllium Copper Post- Plated 100% Sn A = Beryllium Copper Pre-Plated Sn60/Pb40 F = Beryllium Copper Post-Plated Sn60/Pb40	D = WINDING (DD)
CODE:									

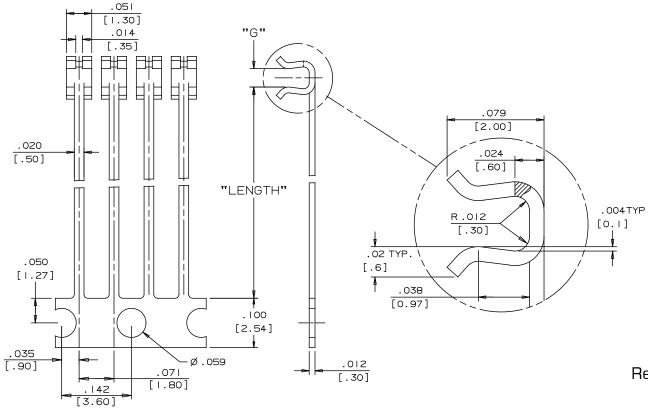
22



.070 [1.778] PITCH



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	N = .070 [1.778]	36AA 36CA	D = Double T = Top S = Bottom O = No Solder	24 = .022(0.558) 30 = .030(0.76) 36 = .036(0.914)	See Chart on Page 11	O = No Stop S = Stop	D = .070[1.77]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									



Drawing Nr.	"Length"
12BA	1.81 [46]
12BB	1.42 [36]
12BC	1.02 [26]
12BD	0.63 [16]

Recommended for LCD's

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	L = .071[1.80]	12BA 12BB 12BC 12BD	0 = No Solder	20 = .020[0.508] 27 = .027[.068] 37 = .037[0.95]	See Chart on Page 11	O = No Stop S = Stop	O = None	S = Phosphor Bronze CDA521 Hard Temper Pre-plated 100% Tin Finish Non RoHS compliant version also available	D = WINDING (DD)
CODE:									

STYLE 0 NO SOLDER

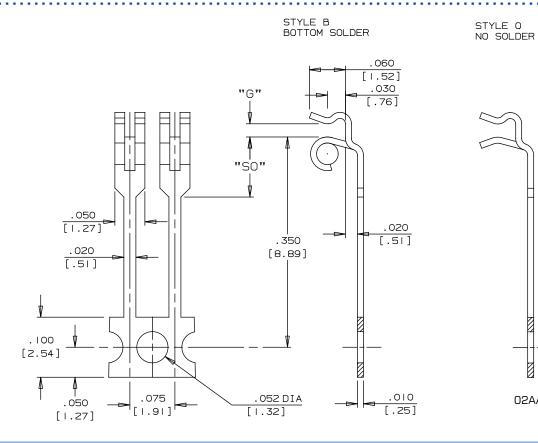
02BA

02AA

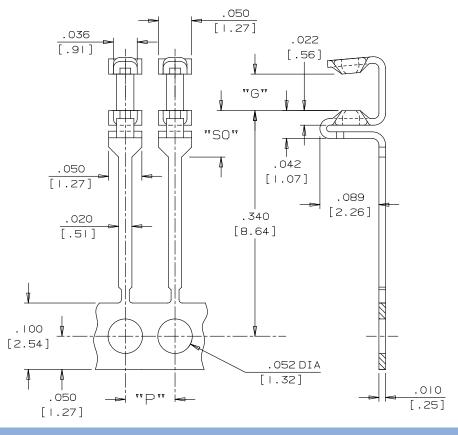
24



075 [1.905] PITCH



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	B = .075[1.905]	02AA 02BA	S = Bottom O = No Solder	22 = .022[0.558] 36 = .036[0.914]	See Chart on Page 11	O = No Stop S = Stop	A = .040[1.00] K = .145[3.68]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

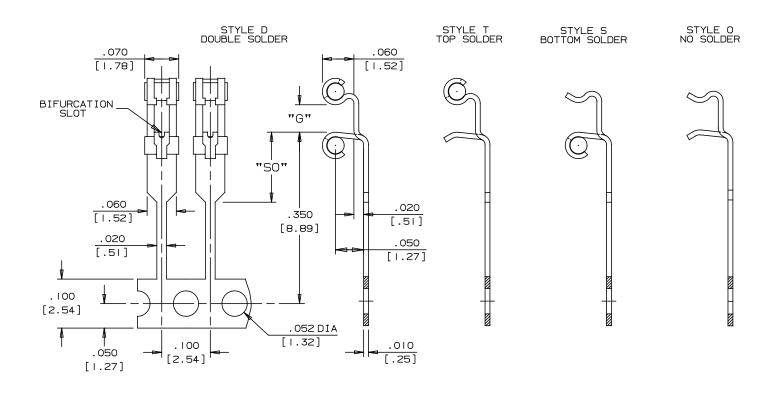


	TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
А	= DIP	B = .075[1.905] H = .150[3.81]	24BA	D = Double	36 = .036[0.914] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	D = .070[1.77]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = WINDING (DD)
C	ODE:									

26



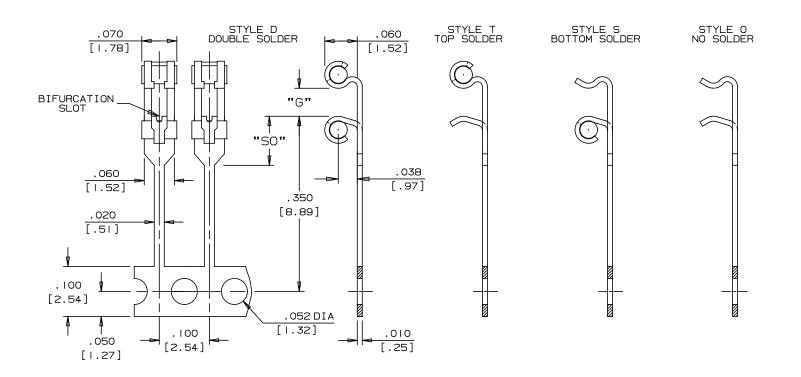
.100 [2.54] PITCH



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	A = .100[2.54]	01AA	D = Double T = Top S = Bottom O = No Solder	22 = .022[0.558] 36 = .036[0.914]	See Chart on Page 11	O = No Stop S = Stop	A = .040[1.00]* D = .070[1.77] K = .145[3.68] *Only available top solder and no solder	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

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		J UUDL.

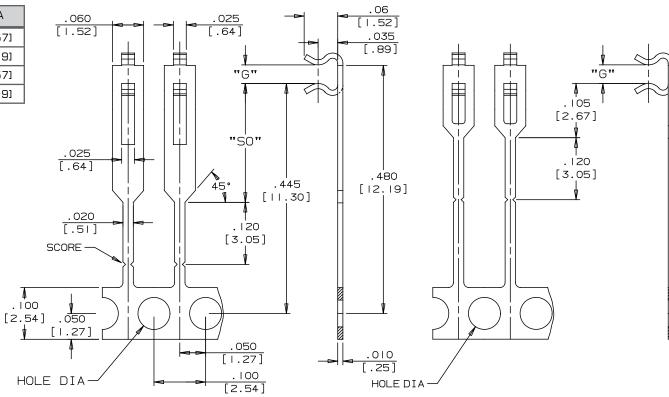
TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	A = .100[2.54]	O8AA	D = Double T = Top S = Bottom O = No Solder	22 = .022[0.558] 36 = .036[0.914] 46 = .046[1.17] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	A = .040[1.00]* D = .070[1.77] K = .145[3.68] Q = .195[4.95] *Only available top solder and no solder	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = WINDING (DD)
CODE:									

28



.100 [2.54] PITCH

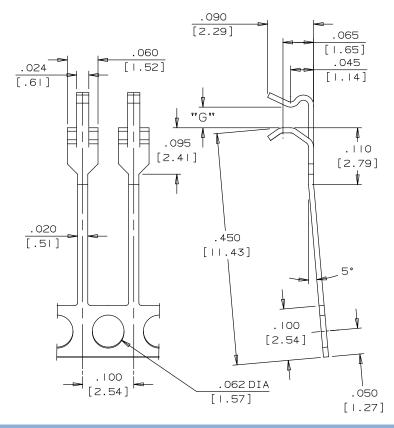
Drawing Nr.	HOLE DIA
08CA	0.062 [1.57]
08CB	0.047 [1.19]
08CC	0.062 [1.57]
08CD	0.047 [1.19]



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	A = .100[2.54]	08CA 08CB 08CC 08CD	0 = No Solder	36 = .036[0.914]	See Chart on Page 11	0 = No Stop S = Stop	X = See Drawing U = .230[5.80]	D = Alloy CA194 Pre- Plated 60/40 Tin Lead Finish Y = Alloy CA194 Pre-Plated 100% Tin Finish	D = Winding (DD)
CODE:									

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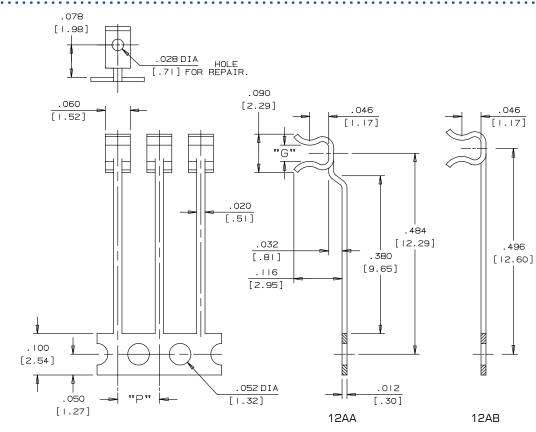


	TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A	= DIP	A = .100[2.54]	11AA	0 = No Solder	22 = .022[0.558] 31 = .031[0.787] 36 = .036[0.914]	See Chart on Page 11	O = No Stop S = Stop	X = See Drawing	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
C	ODE:									

30



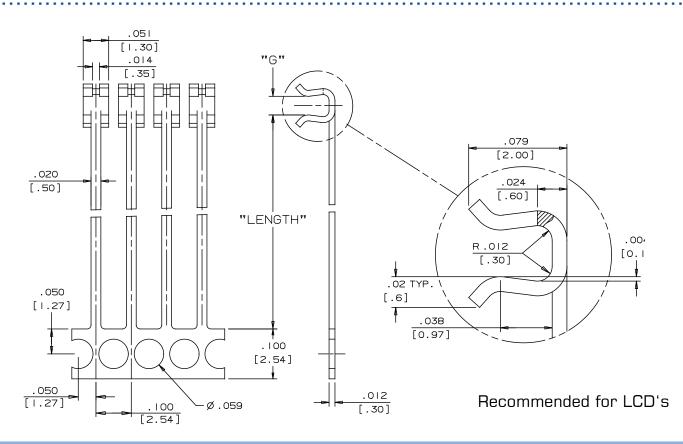
.100 [2.54] PITCH



Recommended for LCD's

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	A = .100[2.54]	12AA 12AB	0 = No Solder	36 = .036[0.914] 41 = .041[1.04] 45 = .045[1.14]	See Chart on Page 11	O = No Stop S = Stop	O = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

Drawing Nr.	"Length"
12CA	1.81 [46]
12CB	1.42 [36]
12CC	1.02 [26]
12CD	0.63 [16]

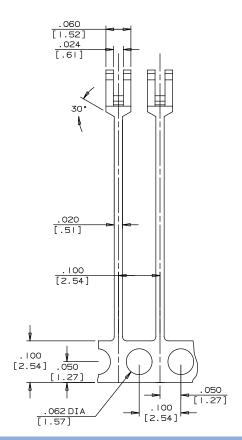


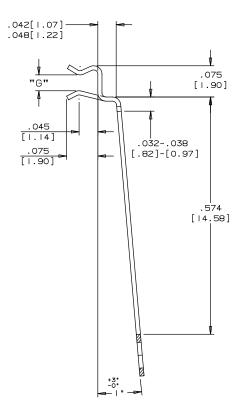
TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	A = .100[2.54]	12CA 12CB 12CC 12CC	0 = No Solder	20 = .020[0.508] 27 = .027[0.68] 37 = .037[0.95]	See Chart on Page 11	O = No Stop S = Stop	O = None	S = Phosphor Bronze CDA521 Hard Temper Pre-Plated 100% Tin Finish Non RoHS compliant version also available	D = Winding (DD)
CODE:									

32



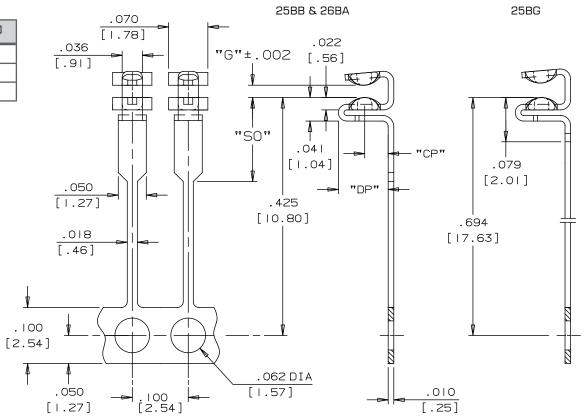
.100 [2.54] PITCH





TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	A = .100[2.54]	14AC	0 = No Solder	38 = .038(0.965)	See Chart on Page 11	O = No Stop S = Stop	X = See Drawing	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

Drawing Nr.	"DP" IN. [MM]	"CP" IN. [MM]
25BB	0.089 [2.26]	0.042 [1.07]
25BG	0.089 [2.26]	0.042 [1.07]
26BA	0.078 [1.98]	0.036 [0.91]

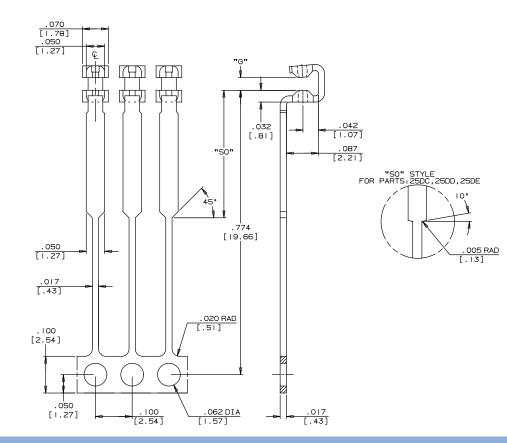


TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	A = .100[2.54]	2588 258G 268A	D = Double T = Top S = Bottom O = No Solder	22 = .022[0.558] 36 = .036[0.914] 46 = .046[1.17] 56 = .056[1.42]	See Chart on Page 11	0 = No Stop S = Stop	E = .080(2.037) L = .150(3.81) T = .220 (5.59)	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

34

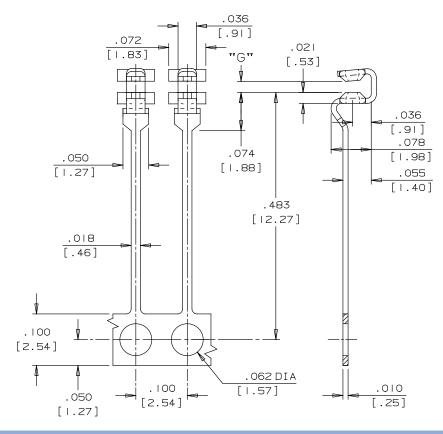


100 [2.54] PITCH



Drawing Nr.	"SO" IN. [MM]
25DA	0.347 [8.81]
25DB	0.370 [9.40]
25DC	0.305 [7.75]
25DD	0.190 [4.83]
25DE	0.275 [6.99]

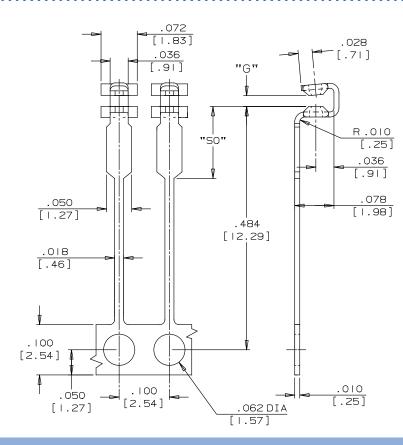
TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	A = .100[2.54]	25DA 25DB 25DC 25DD 25DE	D = Double	31 = .031[0.787] 33 = .033[0.838] 34 = .034[0.864]	See Chart on Page 11	O = No Stop S = Stop	(see table above)	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	A = .100(2.54)	2688	D = Double T = Top S = Bottom O = No Solder	22 = .022[0.558] 36 = .036[0.914] 46 = .046[1.17] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	X = See Drawing	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									



.100 [2.54] PITCH

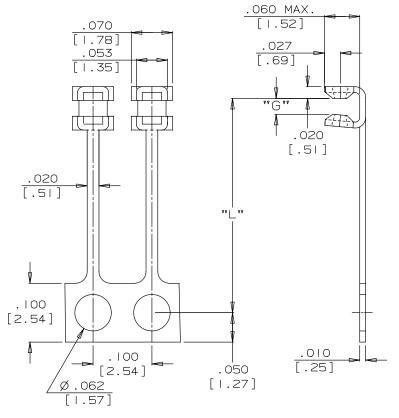


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TY	/PE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = [DIP	A = .100(2.54)	26BC	D = Double T = Top S = Bottom O = No Solder	22 = .022[0.558] 36 = .036[0.914] 46 = .046[1.17] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	D = .070[1.77] K = .145[3.68]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE	≣:									

.100 [2.54] PITCH

Drawing Nr.	"Ľ IN [MM]
32BA	0.364 [9.25]
32BB	0.479 [12.17]



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
A = DIP	A = .100[2.54]	32BA 32BB	D = Double T = Top S = Bottom O = No Solder	18 = .018(0.46) 22 = .022(0.56) 27 = .027(0.69) 32 = .032(0.81) 36 = .036(0.914) 47 = .047(1.19)	See Chart on Page 11	O = No Stop S = Stop	O = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

37

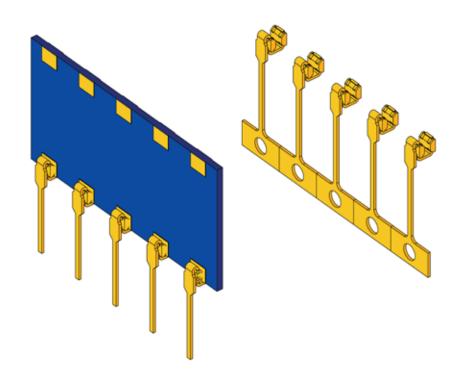




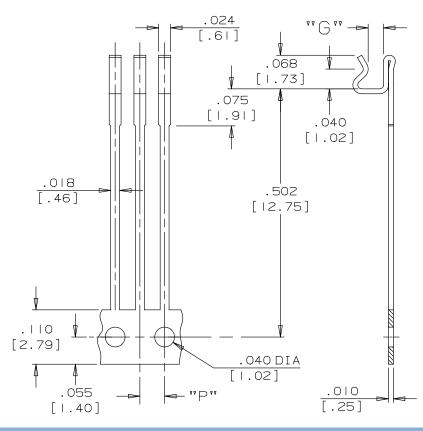


Single Inline Package

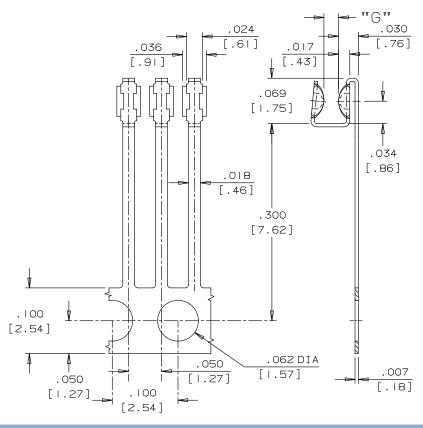
	Dr	rawing N	0.	Pit	cch	Page
06AB				A = .100[2.54]	C = .050[1.27]	40
13AA				C = .050[1.27]		41
36BB				N = .070 [1.778]		42
24AA	24AB			B = .075[1.905]		43
04AA				A = .100[2.54]		44
05AA	05AB			A = .100[2.54]		45
14AA	14AB			A = .100[2.54]		46
15AA				A = .100[2.54]		47
25AB	25AH	25AF		A = .100[2.54]		48
25CA	25CB	25CC	25CD	A = .100[2.54]		49
26AA				A = .100[2.54]		50
26AB				A = .100[2.54]		51
26AC				A = .100[2.54]		52
32AA	32AC			A = .100[2.54]		53



40 .050 [1.27] / .100 [2.54] PITCH



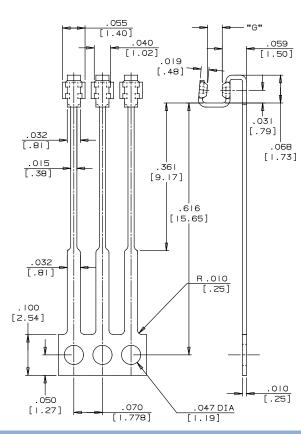
TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
B = SIP	A = .100[2.54] C = .050[1.27]	06AB	0 = No Solder	12 = .012 [0.31] 22 = .022[0.558] 30 = .030 [0.762] 36 = .036[0.914]	See Chart on Page 11	O = No Stop S = Stop	O = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
CODE:									



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
B = SIP	C = .050[1.27]	13AA	D = Double T = Top S = Bottom O = No Solder	22 = .022[0.558] 36 = .036[0.914] 46 = .046 [1.17] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	O = None	X = Beryllium Copper Pre- Plated 100% Sn I = Beryllium Copper Post- Plated 100% Sn A = Beryllium Copper Pre-Plated Sn60/Pb40 F = Beryllium Copper Post-Plated Sn60/Pb40	F = Winding (SB)
CODE:									

42

.070 [1.778] PITCH

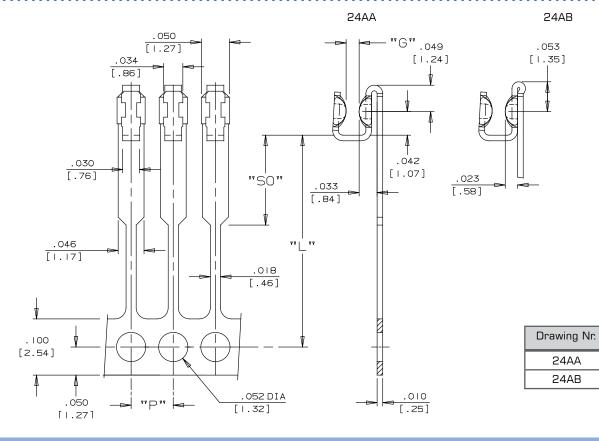


TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
B = SIP	N = .070 [1.778]	36BB	S = Bottom O = No Solder	23 = .023[0.584] 36 = .036[0.914]	See Chart on Page 11	O = No Stop S = Stop	0 = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
CODE:									

"Ľ" IN [MM]

0.377 [9.58]

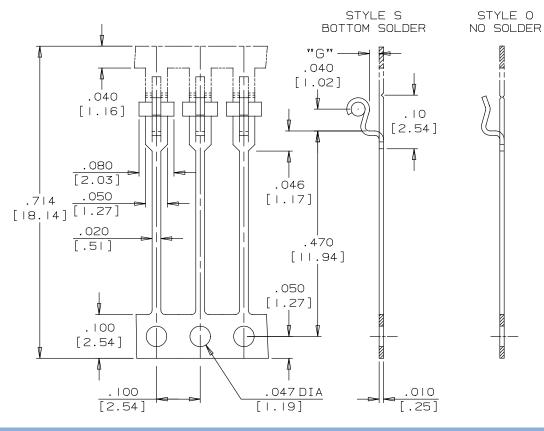
0.497 [12.62]



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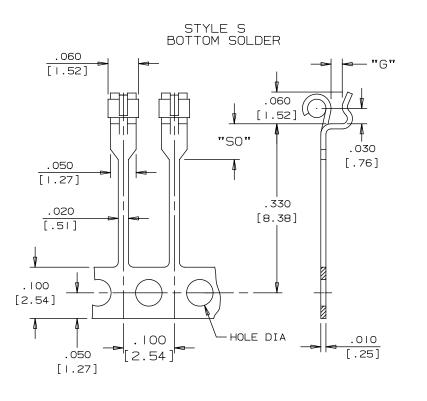
TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
B = SIP	B = .075(1.905)	24AA 24AB	D = Double T = Top S = Bottom O = No Solder	22 = .022(0.558) 36 = .036(0.914) 56 = .056(1.42)	See Chart on Page 11	O = No Stop S = Stop	B = .50 [1.27] M = .160 [4.06]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
CODE:									

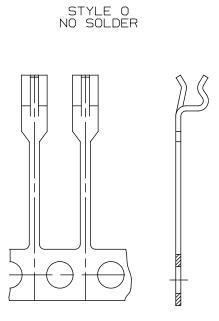
.100 [2.54] PITCH



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	TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
	B = SIP	A = .100[2.54]	04AA	T = Top O = No Solder	22 = .022[0.558] 36 = .036[0.914]	See Chart on Page 11	O = No Stop S = Stop	X = See Drawing	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	H = Winding (SD)
ı	CODE:									





Drawing Nr.	HOLE DIA				
05AA	0.052 [1.32]				
05AB	0.062 [1.57]				

SELECT SPECIFIC OPTIONS TO DETERMINE ORDERING CODE:

TYPE	PITCH	DRWG.	SOLDER	GAP	SOLDER	SOLDER	STAND OFF	MATERIAL/	STANDARD
	(P)	NO.	LOCATION	(G)	TYPE	STOP	(SO)	PLATING	ORIENTATION
B = SIP	A = .100[2.54]	05AA 05AB	S = Bottom O = No Solder	22 = .022(0.558) 26 = .026(0.661) 31 = .031(0.787) 36 = .036(0.914) 41 = .041(1.04) 46 = .046(1.17) 52 = .052(1.32) 56 = .056(1.42) 62 = .062(1.575)	See Chart on Page 11	O = No Stop S = Stop	A = .040[1.00] D = .070[1.77] K = .145[3.68]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)

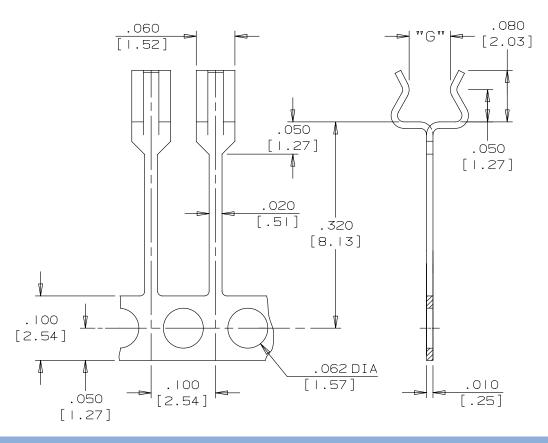
CODE:

.100 [2.54] PITCH

	,
Drawing Nr.	"Ľ IN [MM]
14AA	0.210 [5.33]
14AB	0.610 [15.49]

.024 [.61] .060 [1.52] "SO"	(.028) .075 (.71] .045 (.71)
.100	.062 DIA 2 .010 [.25]

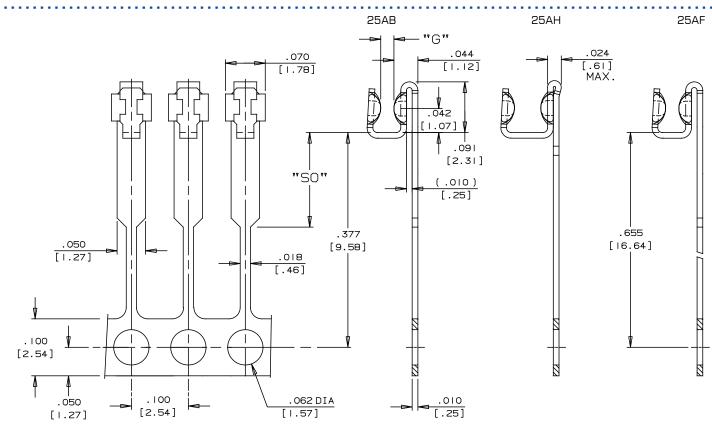
TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
B = SIP	A = .100[2.54]	14AA 14AB	0 = No Solder	22 = .022[0.558] 36 = .036[0.914] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	A = .040[1.00] B = .050[1.27]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
CODE:									



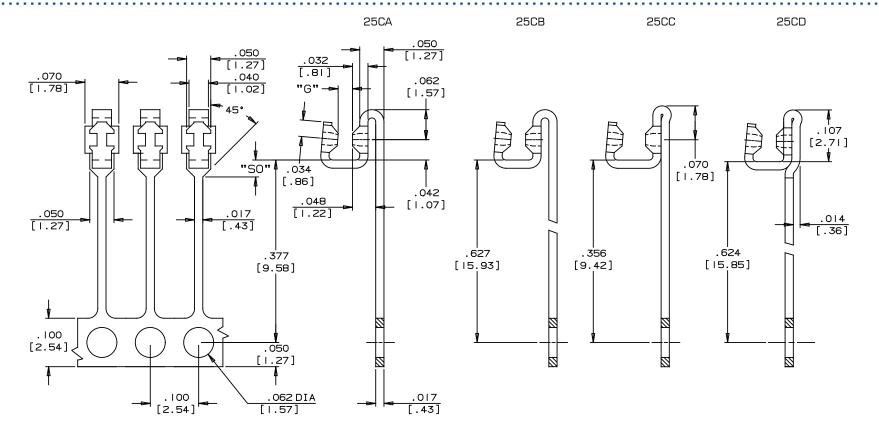
TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
B = SIP	A = .100[2.54]	15AA	0 = No Solderr	22 = .022(0.558) 46 = .046(1.17) 56 = .056(1.42)	See Chart on Page 11	O = No Stop S = Stop	B = .050[1.27]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
CODE:									

Interplex NAS

.100 [2.54] PITCH



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
B = SIP	A = .100[2.54]	25AB 25AH 25AF	D = Double T = Top S = Bottom O = No Solder	22 = .022[0.558] 28 = .028[0.70] 36 = .036[0.914] 46 = .046[1.17] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	A = .040[1.00] E = .080[2.03] F = .090[2.29] N = .170[4.32]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
CODE:									



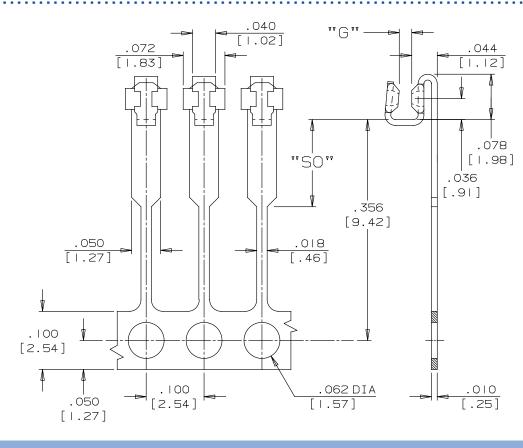
SELECT SPECIFIC OPTIONS TO DETERMINE ORDERING CODE:

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
B = SIP	A = .100[2.54]	25CA 25CB 25CC 25CD	D = Double T = Top S = Bottom O = No Solder	32 = .032[0.813] 36 = .036[0.914]	See Chart on Page 11	O = No Stop S = Stop	A = .040[1.00]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
CODE									

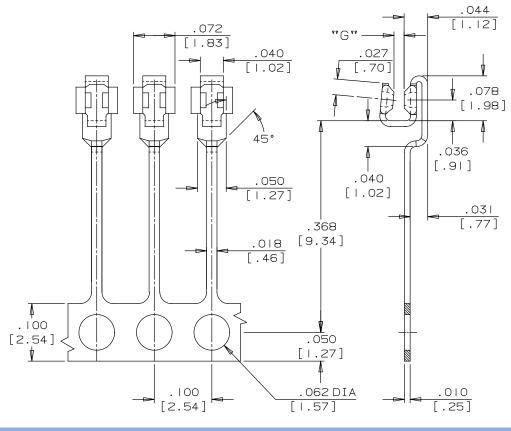
CODE:

50

.100 [2.54] PITCH



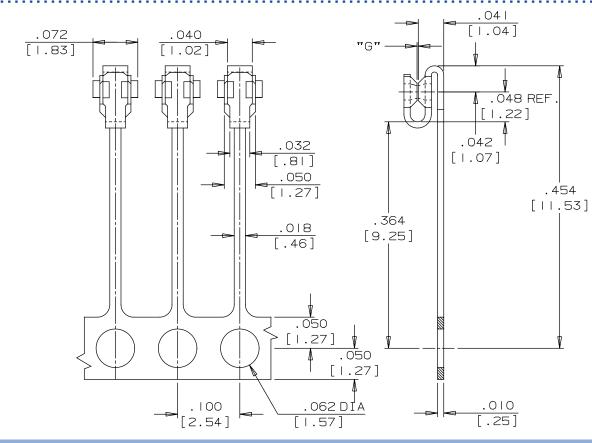
TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
B = SIP	A = .100[2.54]	26AA	D = Double T = Top S = Bottom O = No Solder	18 = .018(0.46) 22 = .022(0.56) 36 = .036(0.914) 46 = .046(1.17) 56 = .056(1.42)	See Chart on Page 11	O = No Stop S = Stop	A = .040[1.00] D = .070[1.77] L = .150[3.81]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
CODE:									



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
B = SIP	A = .100[2.54]	26AB	D = Double T = Top S = Bottom O = No Solder	18 = .018(0.46) 22 = .022(0.56) 36 = .036(0.914) 46 = .046(1.17) 56 = .056(1.42)	See Chart on Page 11	O = No Stop S = Stop	A = .040[1.00]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
CODE:									

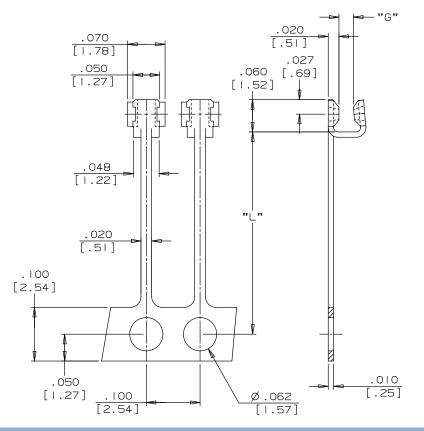
52

.100 [2.54] PITCH



TYPE	PITCH	DRWG.	SOLDER	GAP	SOLDER	SOLDER	STAND OFF	MATERIAL/	STANDARD
	(P)	NO.	LOCATION	(G)	TYPE	STOP	(SO)	PLATING	ORIENTATION
B = SIP	A = .100[2.54]	26AC	D = Double T = Top S = Bottom O = No Solder	02 = .002[0.051] 12 = .012[0.305]	See Chart on Page 11	O = No Stop S = Stop	O = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)

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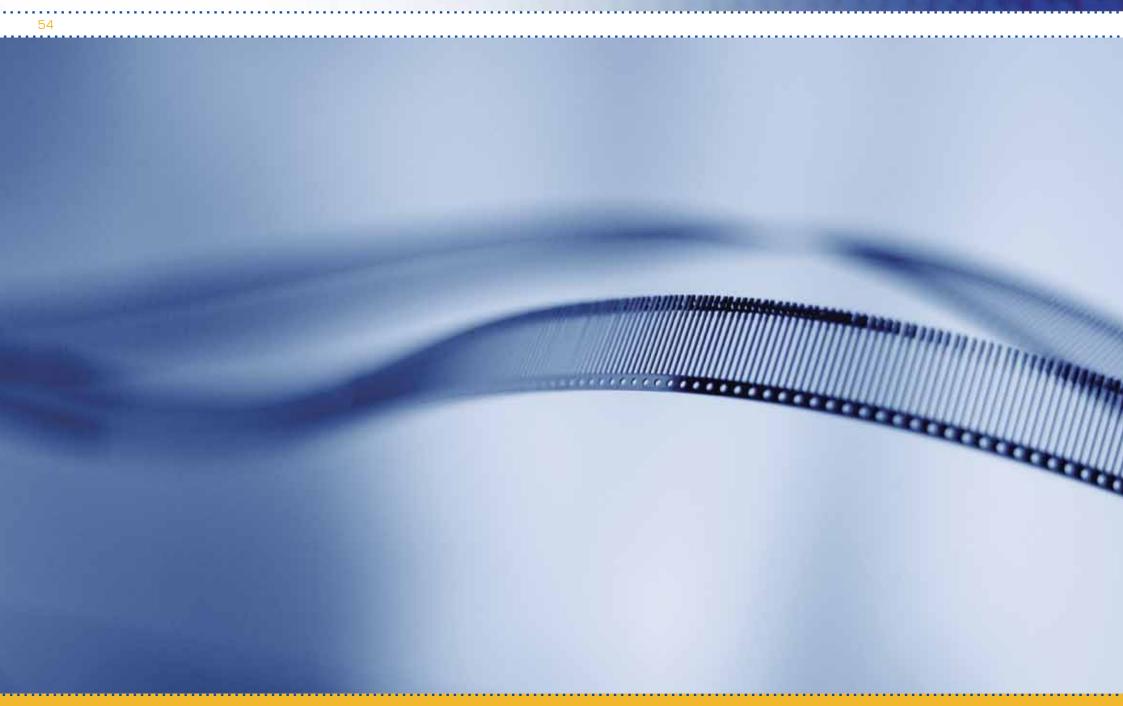


Drawing Nr.	"L" IN. [MM]
32AA	0.377 [9.58]
32AC	0.490 [12.45]

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
B = SIP	A = .100[2.54]	32AA 32AC	D = Double T = Top S = Bottom O = No Solder	18 = .018[0.46] 22 = .022[0.56] 27 = .027[0.69] 32 = .032[0.81] 36 = .036[0.914] 47 = .047[1.19]	See Chart on Page 11	O = No Stop S = Stop	O = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
CODE:									

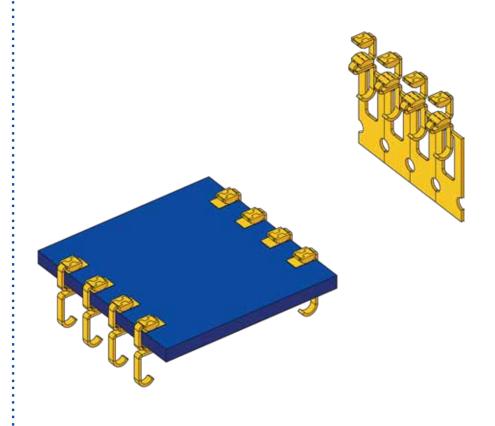






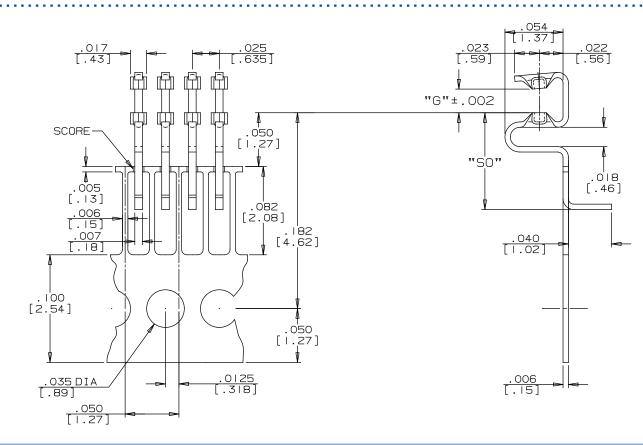
Surface Mount Application

	Dr	rawing N	0.	Pit	tch	Page
21DA				F = .025[0.635]		56
18AA				D = .040[1.02]		57
22AA	22BC			D = .040[1.02]		58
07CA	07CB	O7DA		C = .050[1.27]		59
13CA				C = .050[1.27]		60
17AA	17AB			C = .050[1.27]		61
19AA	19AB			C = .050[1.27]		62
20AA				C = .050[1.27]		63
CC21AA	21BA	21BC		C = .050[1.27]		64
CA21AA	21BA	21AB		A = .100[2.54]		65
21AC	21AD			A = .100[2.54]		66
26CA	26DA	26DD		A = .100[2.54]		67
34AC				A = .100[2.54]		68

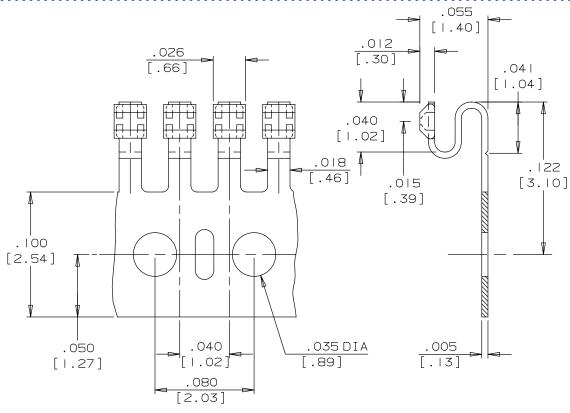




.025 (0.635) PITCH



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
C = SMT	F = .025(0.635)	21DA	D = Double	22 = .022(0.558) 36 = .036(0.914) 43 = .043(1.10)	See Chart on Page 11	O = No Stop S = Stop	D = .070[1.77] F = .090[2.28]	X = Beryllium Copper Pre- Plated 100% Sn I = Beryllium Copper Post- Plated 100% Sn A = Beryllium Copper Pre-Plated Sn60/Pb40 F = Beryllium Copper Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									



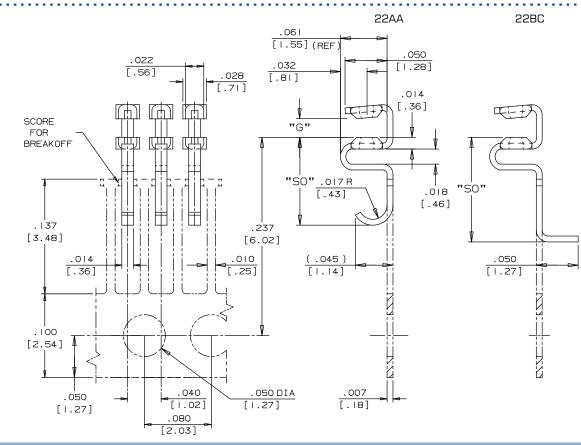
18AA

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
C = SMT	D = .040[1.02]	18AA	S = Bottom	00 = None	See Chart on Page 11	O = No Stop S = Stop	X = See Drawing	M = Beryllium Copper Post-Plated 63/37 Tin Lead Finish I = Beryllium Copper Post-Plated 100% Sn	H = Winding (SD)
CODE:									

58

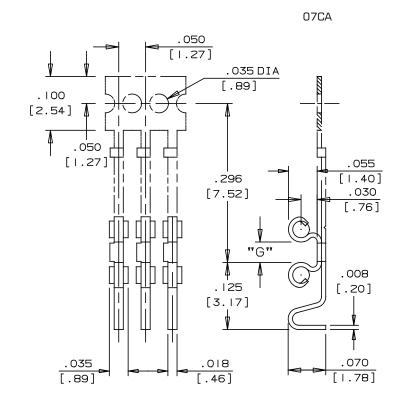


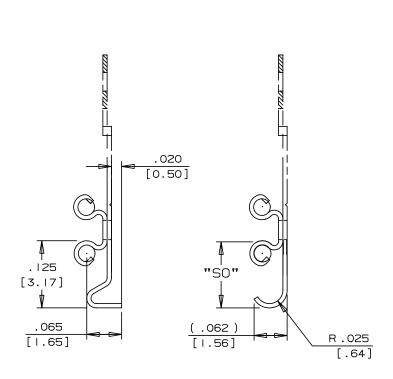
.040 [1.02] PITCH



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
C = SMT	D = .040[1.02]	22AA 22BC	D = Double	22 = .022(0.56) 36 = .036(0.914) 56 = .056(1.42) 72 = .072(1.83)	See Chart on Page 11	O = No Stop S = Stop	E = .080(2.03) H = .100(2.54) J = .125(3.17)* *22BC only	X = Beryllium Copper Pre- Plated 100% Sn I = Beryllium Copper Post- Plated 100% Sn A = Beryllium Copper Pre-Plated Sn60/Pb40 F = Beryllium Copper Post-Plated Sn60/Pb40	D = Winding (DD)
CODE									

07CB

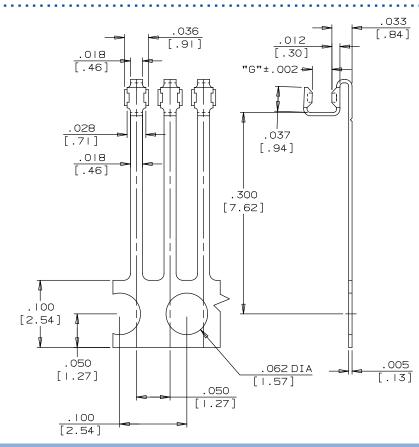




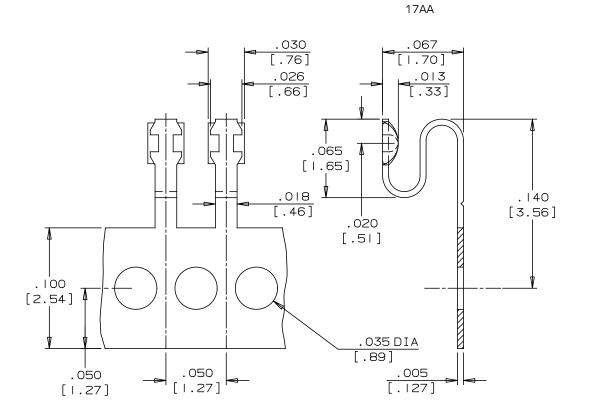
O7DA

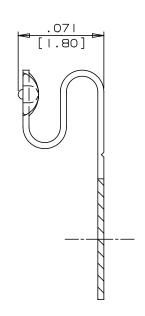
TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
C = SMT	C = .050[1.27]	07CA 07CB 07DA	D = Double T = Top S = Bottom O = No Solder	22 = .022(0.558) 36 = .036(0.914) 56 = .056(1.42)	See Chart on Page 11	O = No Stop S = Stop	J = .125[3.17] F = .090[2.28]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									





TY	PE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
C = S	MT	C = .050[1.27]	13CA	D = Double T = Top S = Bottom O = No Solder	22 = .022(0.558) 27 = .027(0.69)	See Chart on Page 11	O = No Stop S = Stop	(see drawing)	X = Beryllium Copper Pre- Plated 100% Sn I = Beryllium Copper Post- Plated 100% Sn A = Beryllium Copper Pre-Plated Sn60/Pb40 F = Beryllium Copper Post-Plated Sn60/Pb40	D = Winding (DD)
CODE										

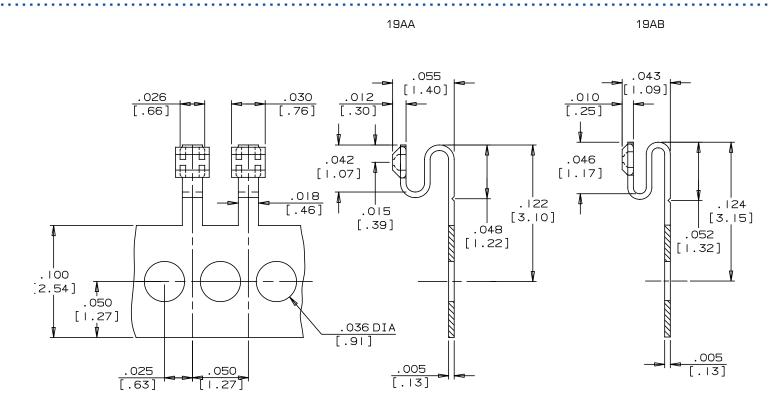




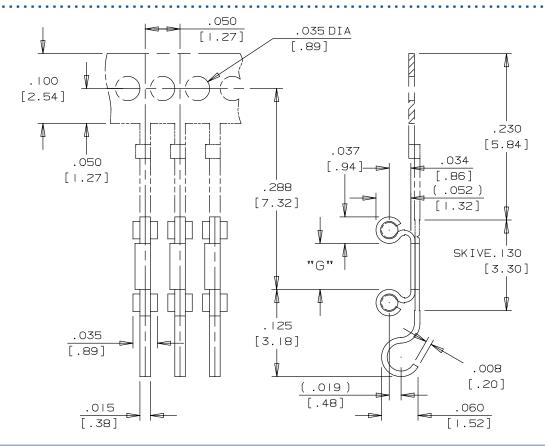
17AB

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
C = SMT	C = .050[1.27]	17AA 17AB	S = Bottom	OO = None	See Chart on Page 11	O = No Stop S = Stop	X = See Drawing	M = Beryllium Copper Post-plated 63/37 Tin Lead Finish I = Beryllium Copper Post- Plated 100% Sn	H = Winding (SD)
CODE:									



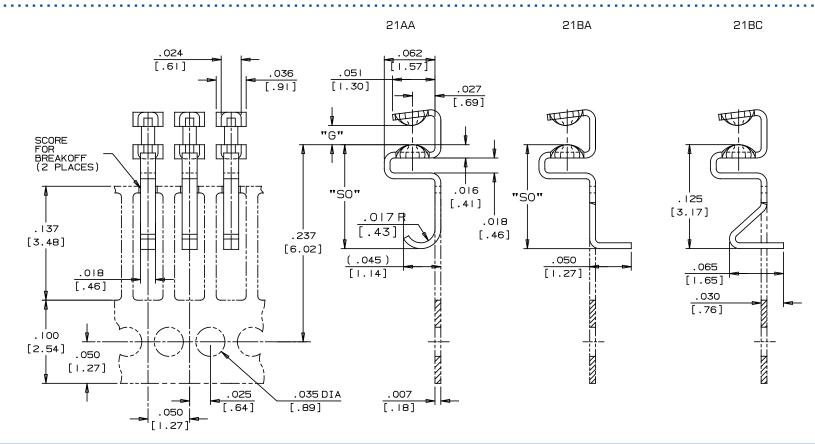


TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
C = SMT	C = .050[1.27]	19AA 19AB	S = Bottom	OO = None	See Chart on Page 11	O = No Stop S = Stop	X = See Drawing	M = Beryllium Copper Post-plated 63/37 Tin Lead Finish I = Beryllium Copper Post- Plated 100% Sn	H = Winding (SD)
CODE:									



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
C = SMT	C = .050[1.27]	20AA	D = Double T = Top S = Bottom O = No Solder	56 = .056(1.42) 66 = .066 (1.676) 68 = .068(1.73) 72 = .072(1.83) 80 = .080 (2.032)	See Chart on Page 11	O = No Stop S = Stop	J = .125[3.17]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

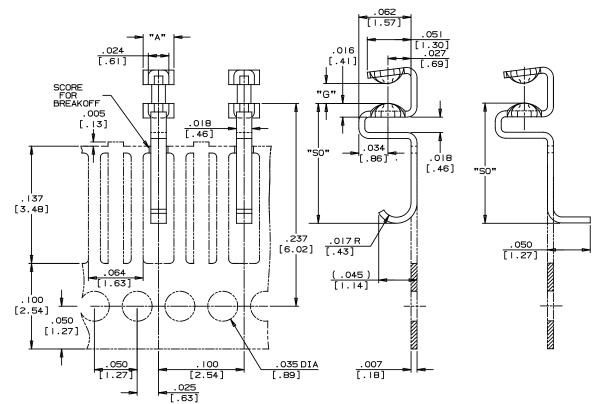




TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
C = SMT	C = .050[1.27]	21AA 21BA 21BC	D = Double	22 = .022(0.56) 36 = .036(0.914) 46 = .046(1.17) 56 = .056(1.42) 72 = .072(1.83)	See Chart on Page 11	O = No Stop S = Stop	D = .070[1.77] F = .090[2.28] J = .125[3.17] K = .145[3.68]	X = Beryllium Copper Pre- Plated 100% Sn I = Beryllium Copper Post- Plated 100% Sn A = Beryllium Copper Pre-Plated Sn60/Pb40 F = Beryllium Copper Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

.100 [2.54] Pitch CA21AA/ CA21AB





Drawing Nr.	DIM "A"					
21AA	0.036 / [.91]					
21BA	0.036 / [.91]					
21AB	0.070 / [1.78]					

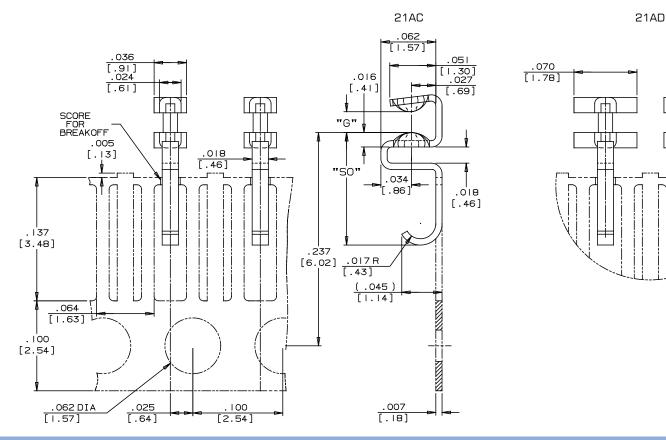
SELECT SPECIFIC OPTIONS TO DETERMINE ORDERING CODE:

TYPE	PITCH	DRWG.	SOLDER	GAP	SOLDER	SOLDER	STAND OFF	MATERIAL/	STANDARD
	(P)	NO.	LOCATION	(G)	TYPE	STOP	(SO)	PLATING	ORIENTATION
C = SMT	A = .100[2.54]	21AA 21BA 21AB	D = Double	22 = .022[0.56] 36 = .036[0.914] 46 = .046[1.17] 56 = .056[1.42] 72 = .072[1.83]	See Chart on Page 11	O = No Stop S = Stop	D = .070[1.77] F = .090[2.28] J = .125[3.17] K = .145[3.68]	X = Beryllium Copper Pre- Plated 100% Sn I = Beryllium Copper Post- Plated 100% Sn A = Beryllium Copper Pre-Plated Sn60/Pb40 F = Beryllium Copper Post-Plated Sn60/Pb40	D = Winding (DD)

CODE:

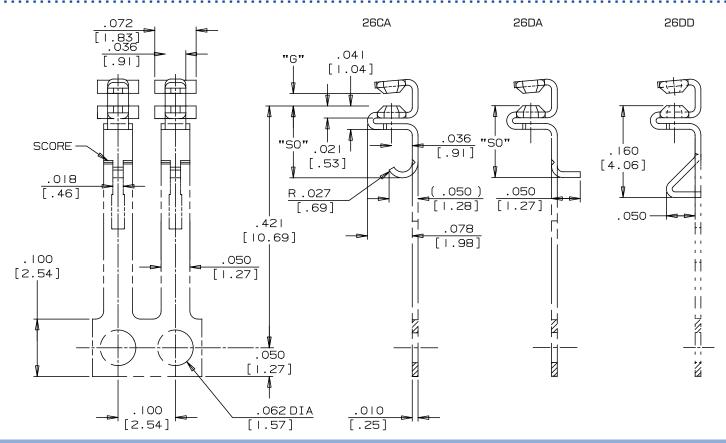


.100 [2.54] PITCH



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
C = SMT	A = .100[2.54]	21AC 21AD	D = Double	22 = .022[0.56] 36 = .036[0.914] 46 = .046[1.17] 56 = .056[1.42] 72 = .072 [1.83]	See Chart on Page 11	O = No Stop S = Stop	D = .070[1.77] F = .090[2.28] J = .125[3.17] K = .145[3.68]	X = Beryllium Copper Pre- Plated 100% Sn I = Beryllium Copper Post- Plated 100% Sn A = Beryllium Copper Pre-Plated Sn60/Pb40 F = Beryllium Copper Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

.100 [2.54] PITCH



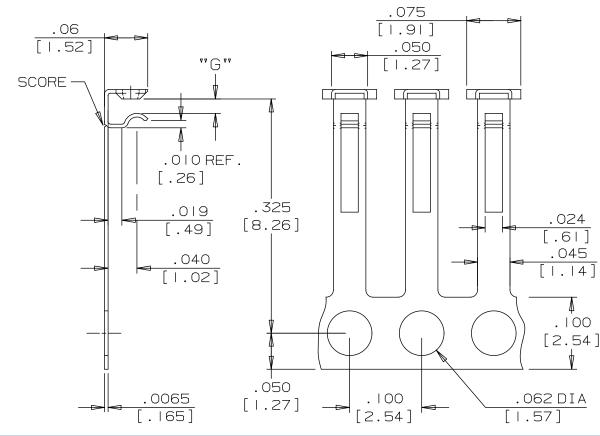
SELECT SPECIFIC OPTIONS TO DETERMINE ORDERING CODE:

TYPE	PITCH	DRWG.	SOLDER	GAP	SOLDER	SOLDER	STAND OFF	MATERIAL/	STANDARD
	(P)	NO.	LOCATION	(G)	TYPE	STOP	(SO)	PLATING	ORIENTATION
C = SMT	A = .100[2.54]	26CA 26DA 26DD	D = Double	18 = .018I0.461 22 = .022I0.561 30 = .030I0.761 36 = .036I0.9141 46 = .046I1.171 56 = .056I1.421	See Chart on Page 11	O = No Stop S = Stop	F = .090(2.28) J = .125(3.17) M = .160(4.06)	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)

CODE:



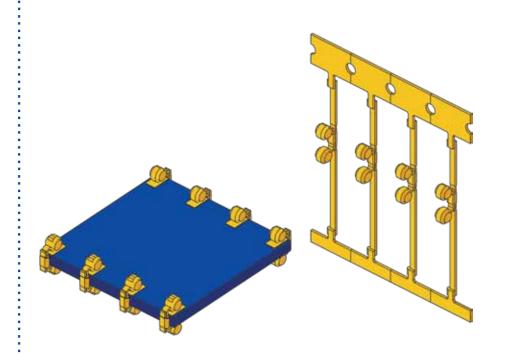
.100 [2.54] PITCH



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
C = SMT	A = .100[2.54]	34AC	Т = Тор	22 = .022(0.56)	See Chart on Page 11	O = No Stop S = Stop	X = See Drawing	S = Nickel Iron Alloy Post-plated 60/40 Tin Lead Finish over Nickel RoHS available	D = Winding (DD)
CODE:									

Shorting Clip Interconnect

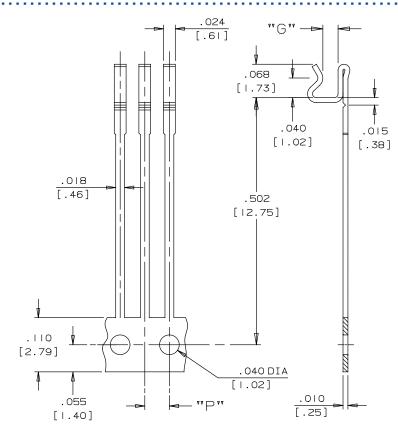
Drawing No.		Pitch			
06AA	C = .05	60 [1.27] A = .	100[2.54] 70		
07AB	C = .05	60 [1.27] A = .	100[2.54] 71		



70

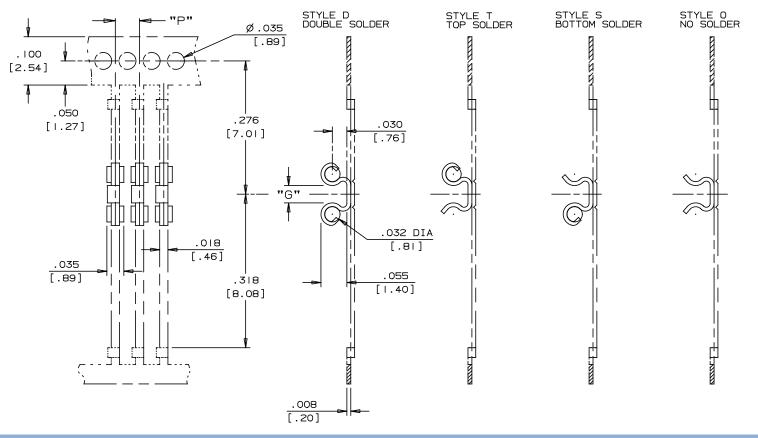
Interplex NAS

.050 [1.27] / .100 [2.54] PITCH



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
D = SCI	A = .100[2.54] C = .050[1.27]	06AA	0 = No Solder	12 = .012(0.305) 22 = .022(0.56) 32 = .032(0.813) 36 = .036(0.914)	See Chart on Page 11	O = No Stop S = Stop	0 = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
CODE:									

.050 [1.27] / .100 [2.54] PITCH



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TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
D = SCI	A = .100[2.54] C = .050[1.27]	07AB	D = Double T = Top S = Bottom O = No Solder	22 = .022(0.558) 36 = .036(0.914) 56 = .056(1.42)	See Chart on Page 11	O = No Stop S = Stop	O = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

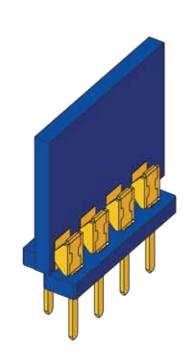


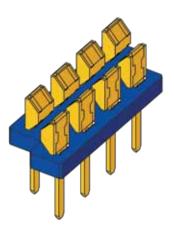




Dual Row Interconnects

	Dr	rawing N	0.	Pitch	Page
20XX				.100[2.54] X .050 [1.27]0FFSET	74
21XX				.100[2.54] X .050 [1.27]0FFSET	75
22XX				.100[2.54] X .050 [1.27]0FFSET	76
23XX				.100[2.54] X .100 [2.54]INLINE	77
24XX				.100[2.54] X .050 [1.27]0FFSET	78
25XX				.100(2.54) X .100 (2.54)INLINE	79
26XX				.100[2.54] X .050 [1.27]0FFSET	80
27XX				.100[2.54] X .050 [1.27]0FFSET	81
28XX				.100[2.54] X .100 [2.54]INLINE	82
1419				.050 [1.27] X .025 [0.635] OFFSET	83





Nr. of Pins

30X2

31X2

32X2

33X2

34X2

35X2

36X2

Drawing Nr.

2030

2031

2032

2033

2034

2035

2036

"K" DIM IN. [MM]

2.900 [73.66]

3.000 [76.20]

3.100 [78.74]

3.200 [81.28]

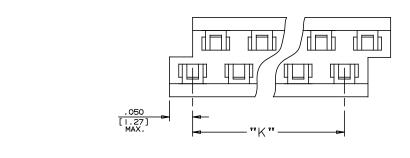
3.300 [83.82]

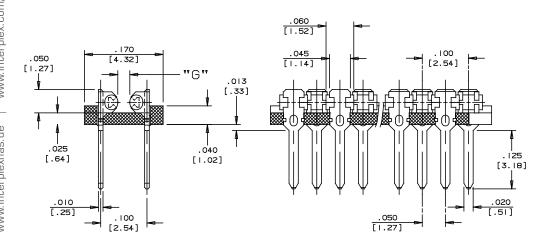
3.400 [86.36]

3.500 [88.90]

74

.100 [2.54] X .050 [1.27] OFFSET





Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]
2010	10X2	0.900 (22.86)
2011	11X2	1.000 [25.40]
2012	12X2	1.100 [27.94]
2013	13X2	1.200 [30.48]
2014	14X2	1.300 (33.02)
2015	15X2	1.400 [35.56]
2016	16X2	1.500 [38.10]
2017	17X2	1.600 [40.64]
2018	18X2	1.700 [43.18]
2019	19X2	1.800 [45.72]
2020	20X2	1.900 [48.26]
2021	21X2	2.000 (50.80)
2022	22X2	2.100 [53.34]
2023	23X2	2.200 (55.88)
2024	24X2	2.300 [58.42]
2025	25X2	2.400 [60.96]
2026	26X2	2.500 [63.50]
2027	27X2	2.600 [66.04]
2028	28X2	2.700 [68.58]
2029	29X2	2.800 [71.12]

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
E = DRI	A = .100[2.54]	20XX	D = Double	44 = .044[1.12] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	0 = None	C = Phosphor Bronze Pre-plated 60/40 Tin Lead Finish E = Phosphor Bronze Pre-Plated 100% Sn Plastic = Liquid Crystal Vectra A-130	N/A
CODE:									

18X2

19X2

20X2

21X2

22X2

23X2

24X2

25X2

26X2

27X2

28X2

29X2

2118

2119

2120

2121

2122

2123

2124

2125

2126

2127

2128

2129

1.700 [43.18]

1.800 [45.72]

1.900 [48.26]

2.000 [50.80]

2.100 [53.34]

2.200 [55.88]

2.300 [58.42]

2.400 [60.96]

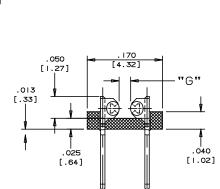
2.500 [63.50]

2.600 [66.04]

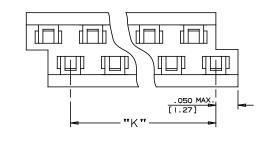
2.700 [68.58]

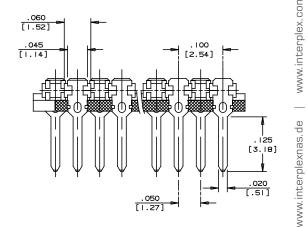
2.800 [71.12]

Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]	Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]
2110	10X2	0.900 [22.86]	2130	30X2	2.900 [73.66]
2111	11X2	1.000 [25.40]	2131	31X2	3.000 [76.20]
2112	12X2	1.100 [27.94]	2132	32X2	3.100 [78.74]
2113	13X2	1.200 [30.48]	2133	33X2	3.200 [81.28]
2114	14X2	1.300 [33.02]	2134	34X2	3.300 [83.82]
2115	15X2	1.400 [35.56]	2135	35X2	3.400 [86.36]
2116	16X2	1.500 [38.10]	2136	36X2	3.500 [88.90]
2117	17X2	1.600 [40.64]			



.100 [2.54]



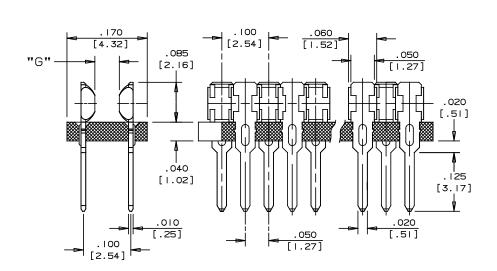


TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
E = DRI	A = .100[2.54]	21XX	D = Double	44 = .044[1.12] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	O = None	C = Phosphor Bronze Pre-plated 60/40 Tin Lead Finish E = Phosphor Bronze Pre-Plated 100% Sn Plastic = Liquid Crystal Vectra A-130	N/A
CODE:									

Interplex NAS

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.100 [2.54] X .050 [1.27] OFFSET

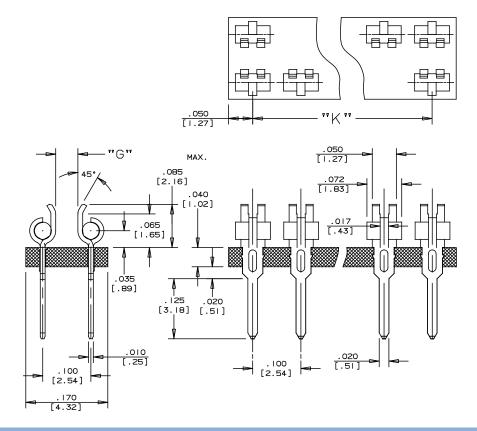


Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]	Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]
2210	10X2	0.900 [22.86]	2231	31X2	3.000 [76.20]
2211	11X2	1.000 [25.40]	2232	32X2	3.100 [78.74]
2212	12X2	1.100 [27.94]	2233	33X2	3.200 [81.28]
2213	13X2	1.200 [30.48]	2234	34X2	3.300 [83.82]
2214	14X2	1.300 [33.02]	2235	35X2	3.400 [86.36]
2215	15X2	1.400 [35.56]	2236	36X2	3.500 [88.90]
2216	16X2	1.500 [38.10]	2237	37X2	3.600 [91.44]
2217	17X2	1.600 [40.64]	2238	38X2	3.700 [93.98]
2218	18X2	1.700 [43.18]	2239	39X2	3.800 (96.52)
2219	19X2	1.800 [45.72]	2240	40X2	3.900 (99.06)
2220	20X2	1.900 [48.26]	2241	41X2	4.000 [101.60]
2221	21X2	2.000 [50.80]	2242	42X2	4.100 [104.14]
2222	22X2	2.100 [53.34]	2243	43X2	4.200 [106.68]
2223	23X2	2.200 [55.88]	2244	44X2	4.300 [109.22]
2224	24X2	2.300 [58.42]	2245	45X2	4.400 [111.76]
2225	25X2	2.400 [60.96]	2246	46X2	4.500 [114.30]
2226	26X2	2.500 [63.50]	2247	47X2	4.600 [116.84]
2227	27X2	2.600 [66.04]	2248	48X2	4.700 [119.38]
2228	28X2	2.700 [68.58]	2249	49X2	4.800 [121.92]
2229	29X2	2.800 [71.12]	2250	50X2	4.900 [124.46]
2230	30X2	2.900 [73.66]			

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
E = DRI	A = .100(2.54)	22XX	D = Double	44 = .044[1.12] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	O = None	C = Phosphor Bronze Pre-plated 60/40 Tin Lead Finish E = Phosphor Bronze Pre-Plated 100% Sn Plastic = Liquid Crystal Vectra A-130	N/A
CODE:									

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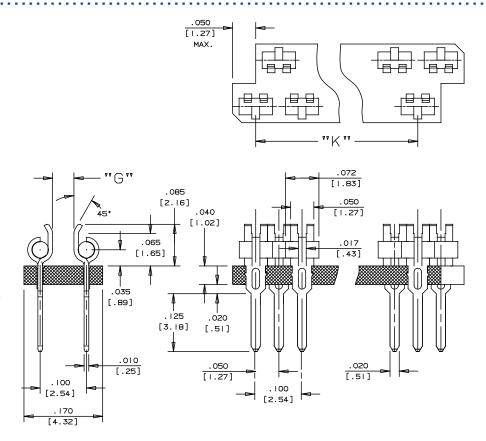
Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]	Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]
2310	10X2	0.900 (22.86)	2331	31X2	3.000 [76.20]
2311	11X2	1.000 [25.40]	2332	32X2	3.100 [78.74]
2312	12X2	1.100 [27.94]	2333	33X2	3.200 [81.28]
2313	13X2	1.200 [30.48]	2334	34X2	3.300 [83.82]
2314	14X2	1.300 [33.02]	2335	35X2	3.400 [86.36]
2315	15X2	1.400 [35.56]	2336	36X2	3.500 [88.90]
2316	16X2	1.500 [38.10]	2337	37X2	3.600 [91.44]
2317	17X2	1.600 [40.64]	2338	38X2	3.700 [93.98]
2318	18X2	1.700 [43.18]	2339	39X2	3.800 (96.52)
2319	19X2	1.800 [45.72]	2340	40X2	3.900 (99.06)
2320	20X2	1.900 [48.26]	2341	41X2	4.000 [101.60]
2321	21X2	2.000 [50.80]	2342	42X2	4.100 [104.14]
2322	22X2	2.100 [53.34]	2343	43X2	4.200 [106.68]
2323	23X2	2.200 [55.88]	2344	44X2	4.300 [109.22]
2324	24X2	2.300 [58.42]	2345	45X2	4.400 [111.76]
2325	25X2	2.400 [60.96]	2346	46X2	4.500 [114.30]
2326	26X2	2.500 [63.50]	2347	47X2	4.600 [116.84]
2327	27X2	2.600 [66.04]	2348	48X2	4.700 [119.38]
2328	28X2	2.700 [68.58]	2349	49X2	4.800 [121.92]
2329	29X2	2.800 [71.12]	2350	50X2	4.900 [124.46]
2330	30X2	2.900 [73.66]			



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
E = DRI	A = .100(2.54)	23XX	D = Double	44 = .044[1.12] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	0 = None	C = Phosphor Bronze Pre-plated 60/40 Tin Lead Finish E = Phosphor Bronze Pre-Plated 100% Sn Plastic = Liquid Crystal Vectra A-130	N/A
CODE:									

Interplex NAS

.100 [2.54] X .050 [1.27] OFFSET

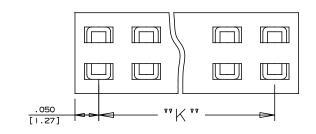


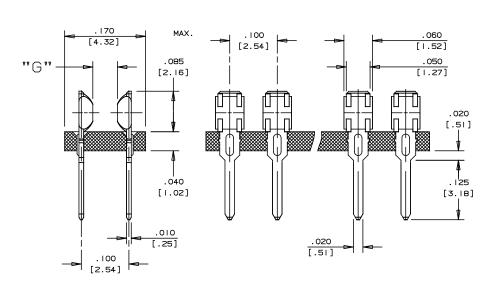
Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]	Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]
2410	10X2	0.900 [22.86]	2431	31X2	3.000 [76.20]
2411	11X2	1.000 [25.40]	2432	32X2	3.100 [78.74]
2412	12X2	1.100 [27.94]	2433	33X2	3.200 [81.28]
2413	13X2	1.200 [30.48]	2434	34X2	3.300 [83.82]
2414	14X2	1.300 [33.02]	2435	35X2	3.400 [86.36]
2415	15X2	1.400 [35.56]	2436	36X2	3.500 [88.90]
2416	16X2	1.500 [38.10]	2437	37X2	3.600 [91.44]
2417	17X2	1.600 [40.64]	2438	38X2	3.700 [93.98]
2418	18X2	1.700 [43.18]	2439	39X2	3.800 (96.52)
2419	19X2	1.800 [45.72]	2440	40X2	3.900 (99.06)
2420	20X2	1.900 [48.26]	2441	41X2	4.000 [101.60]
2421	21X2	2.000 [50.80]	2442	42X2	4.100 [104.14]
2422	22X2	2.100 [53.34]	2443	43X2	4.200 [106.68]
2423	23X2	2.200 [55.88]	2444	44X2	4.300 [109.22]
2424	24X2	2.300 [58.42]	2445	45X2	4.400 [111.76]
2425	25X2	2.400 [60.96]	2446	46X2	4.500 [114.30]
2426	26X2	2.500 [63.50]	2447	47X2	4.600 [116.84]
2427	27X2	2.600 [66.04]	2448	48X2	4.700 [119.38]
2428	28X2	2.700 [68.58]	2449	49X2	4.800 [121.92]
2429	29X2	2.800 [71.12]	2450	50X2	4.900 [124.46]
2430	30X2	2.900 [73.66]			

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
E = DRI	A = .100[2.54]	24XX	D = Double	44 = .044[1.12] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	O = None	C = Phosphor Bronze Pre-plated 60/40 Tin Lead Finish E = Phosphor Bronze Pre-Plated 100% Sn Plastic = Liquid Crystal Vectra A-130	N/A
CODE:									

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Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]	Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]
2510	10X2	0.900 [22.86]	2531	31X2	3.000 [76.20]
2511	11X2	1.000 [25.40]	2532	32X2	3.100 [78.74]
2512	12X2	1.100 [27.94]	2533	33X2	3.200 [81.28]
2513	13X2	1.200 [30.48]	2534	34X2	3.300 [83.82]
2514	14X2	1.300 [33.02]	2535	35X2	3.400 [86.36]
2515	15X2	1.400 [35.56]	2536	36X2	3.500 [88.90]
2516	16X2	1.500 [38.10]	2537	37X2	3.600 [91.44]
2517	17X2	1.600 [40.64]	2538	38X2	3.700 [93.98]
2518	18X2	1.700 [43.18]	2539	39X2	3.800 (96.52)
2519	19X2	1.800 [45.72]	2540	40X2	3.900 (99.06)
2520	20X2	1.900 [48.26]	2541	41X2	4.000 [101.60]
2521	21X2	2.000 [50.80]	2542	42X2	4.100 [104.14]
2522	22X2	2.100 [53.34]	2543	43X2	4.200 [106.68]
2523	23X2	2.200 [55.88]	2544	44X2	4.300 [109.22]
2524	24X2	2.300 [58.42]	2545	45X2	4.400 [111.76]
2525	25X2	2.400 [60.96]	2546	46X2	4.500 [114.30]
2526	26X2	2.500 [63.50]	2547	47X2	4.600 [116.84]
2527	27X2	2.600 [66.04]	2548	48X2	4.700 [119.38]
2528	28X2	2.700 [68.58]	2549	49X2	4.800 [121.92]
2529	29X2	2.800 [71.12]	2550	50X2	4.900 [124.46]
2530	30X2	2.900 [73.66]			

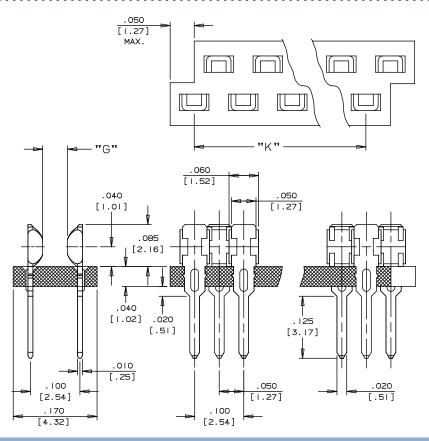




TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
E = DRI	A = .100[2.54]	25XX	D = Double	44 = .044[1.12] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	O = None	C = Phosphor Bronze Pre-plated 60/40 Tin Lead Finish E = Phosphor Bronze Pre-Plated 100% Sn Plastic = Liquid Crystal Vectra A-130	N/A
CODE:									

Interplex NAS

. 100 [2.54] X . 050 [1.27] OFFSET

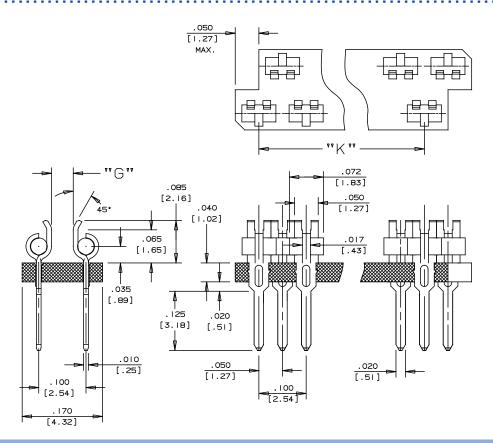


Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]	Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]
2610	10X2	0.900 [22.86]	2631	31X2	3.000 [76.20]
2611	11X2	1.000 [25.40]	2632	32X2	3.100 [78.74]
2612	12X2	1.100 [27.94]	2633	33X2	3.200 [81.28]
2613	13X2	1.200 [30.48]	2634	34X2	3.300 [83.82]
2614	14X2	1.300 [33.02]	2635	35X2	3.400 [86.36]
2615	15X2	1.400 [35.56]	2636	36X2	3.500 [88.90]
2616	16X2	1.500 [38.10]	2637	37X2	3.600 [91.44]
2617	17X2	1.600 [40.64]	2638	38X2	3.700 [93.98]
2618	18X2	1.700 [43.18]	2639	39X2	3.800 [96.52]
2619	19X2	1.800 [45.72]	2640	40X2	3.900 (99.06)
2620	20X2	1.900 [48.26]	2641	41X2	4.000 [101.60]
2621	21X2	2.000 [50.80]	2642	42X2	4.100 [104.14]
2622	22X2	2.100 [53.34]	2643	43X2	4.200 [106.68]
2623	23X2	2.200 [55.88]	2644	44X2	4.300 [109.22]
2624	24X2	2.300 [58.42]	2645	45X2	4.400 [111.76]
2625	25X2	2.400 [60.96]	2646	46X2	4.500 [114.30]
2626	26X2	2.500 [63.50]	2647	47X2	4.600 [116.84]
2627	27X2	2.600 [66.04]	2648	48X2	4.700 [119.38]
2628	28X2	2.700 [68.58]	2649	49X2	4.800 [121.92]
2629	29X2	2.800 [71.12]	2650	50X2	4.900 [124.46]
2630	30X2	2.900 [73.66]			

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
E = DRI	A = .100(2.54)	26XX	D = Double	44 = .044[1.12] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	O = None	C = Phosphor Bronze Pre-plated 60/40 Tin Lead Finish E = Phosphor Bronze Pre-Plated 100% Sn Plastic = Liquid Crystal Vectra A-130	N/A
CODE:									

. 100 [2.54] X . 050 [1.27] OFFSET

Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]	Drawing Nr.	Nr. of Pins	"K" DIM IN. [MM]
2710	10X2	0.900 [22.86]	2731	31X2	3.000 [76.20]
2711	11X2	1.000 [25.40]	2732	32X2	3.100 [78.74]
2712	12X2	1.100 [27.94]	2733	33X2	3.200 [81.28]
2713	13X2	1.200 [30.48]	2734	34X2	3.300 (83.82)
2714	14X2	1.300 [33.02]	2735	35X2	3.400 [86.36]
2715	15X2	1.400 [35.56]	2736	36X2	3.500 (88.90)
2716	16X2	1.500 [38.10]	2737	37X2	3.600 [91.44]
2717	17X2	1.600 [40.64]	2738	38X2	3.700 [93.98]
2718	18X2	1.700 [43.18]	2739	39X2	3.800 (96.52)
2719	19X2	1.800 [45.72]	2740	40X2	3.900 (99.06)
2720	20X2	1.900 [48.26]	2741	41X2	4.000 [101.60]
2721	21X2	2.000 [50.80]	2742	42X2	4.100 [104.14]
2722	22X2	2.100 [53.34]	2743	43X2	4.200 [106.68]
2723	23X2	2.200 [55.88]	2744	44X2	4.300 [109.22]
2724	24X2	2.300 [58.42]	2745	45X2	4.400 [111.76]
2725	25X2	2.400 [60.96]	2746	46X2	4.500 [114.30]
2726	26X2	2.500 [63.50]	2747	47X2	4.600 [116.84]
2727	27X2	2.600 [66.04]	2748	48X2	4.700 [119.38]
2728	28X2	2.700 [68.58]	2749	49X2	4.800 [121.92]
2729	29X2	2.800 [71.12]	2750	50X2	4.900 [124.46]
2730	30X2	2.900 [73.66]			



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
E = DRI	A = .100[2.54]	27XX	D = Double	44 = .044[1.12] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	O = None	C = Phosphor Bronze Pre-plated 60/40 Tin Lead Finish E = Phosphor Bronze Pre-Plated 100% Sn Plastic = Liquid Crystal Vectra A-130	N/A
CODE:									

Nr. of Pins

30X2

31X2

32X2

33X2

34X2

35X2

36X2

"K" DIM IN. [MM]

2.900 [73.66]

3.000 [76.20]

3.100 [78.74]

3.200 [81.28]

3.300 [83.82]

3.400 [86.36]

3.500 [88.90]

Drawing Nr.

2830

2831

2832

2833

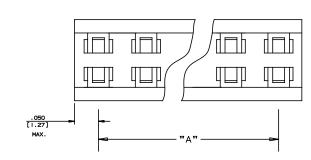
2834

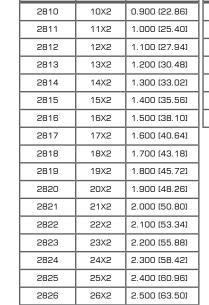
2835

2836

Interplex NAS

.100 [2.54] X .100 [2.54] INLINE





27X2

28X2

29X2

2.600 [66.04]

2.700 [68.58]

2.800 [71.12]

Nr. of Pins

Drawing Nr.

2827

2828

2829

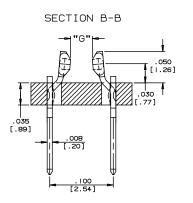
"K" DIM IN. [MM]

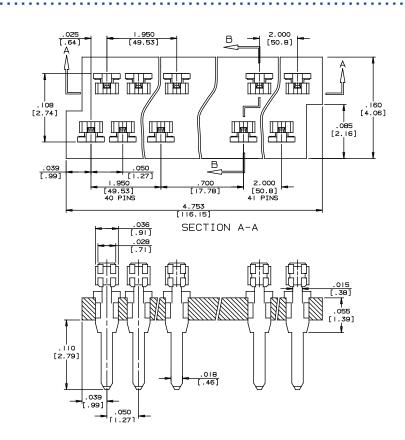
.050 [1.27]	.013 [.33]	(1.14)	
.100			

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
E = DRI	A = .100[2.54]	28XX	D = Double	44 = .044[1.12] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	O = None	C = Phosphor Bronze Pre-plated 60/40 Tin Lead Finish E = Phosphor Bronze Pre-Plated 100% Sn Plastic = Liquid Crystal Vectra A-130	N/A
CODE:									

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81 X 2 = 162 PINS

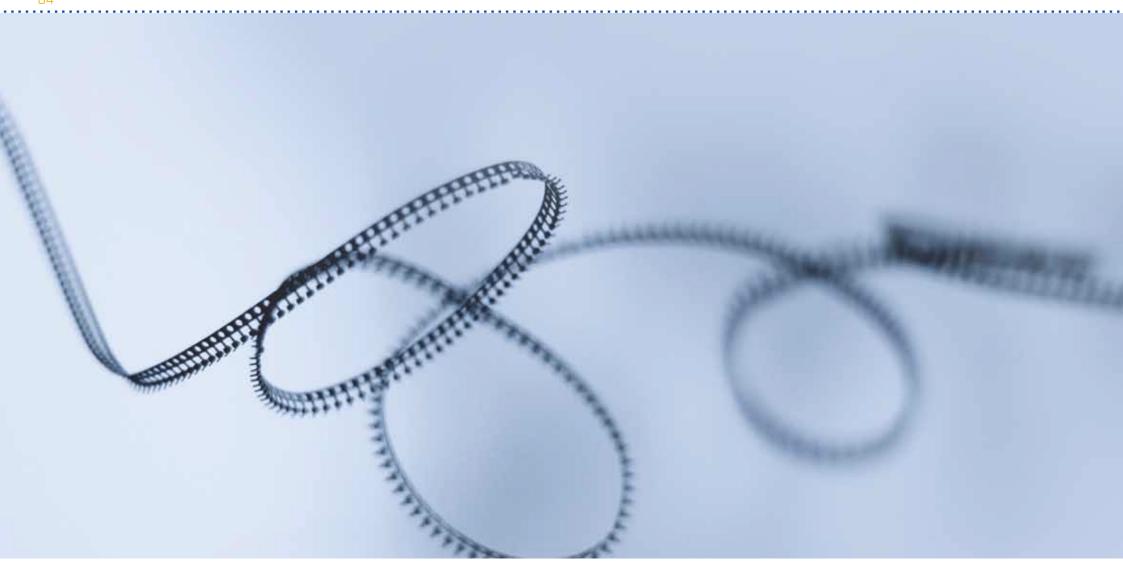




TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
E = DRI	C = .050(1.27)	1419	D = Double	44 = .044[1.12] 56 = .056[1.42]	See Chart on Page 11	O = No Stop S = Stop	0 = None	C = Phosphor Bronze Pre-plated 60/40 Tin Lead Finish E = Phosphor Bronze Pre-Plated 100% Sn Plastic = Celanese For- tron 1140-L4 Color Black	N/A
CODE:									

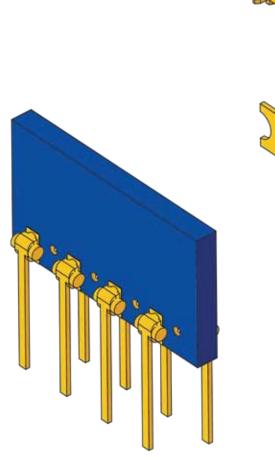


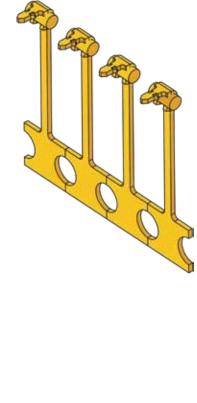




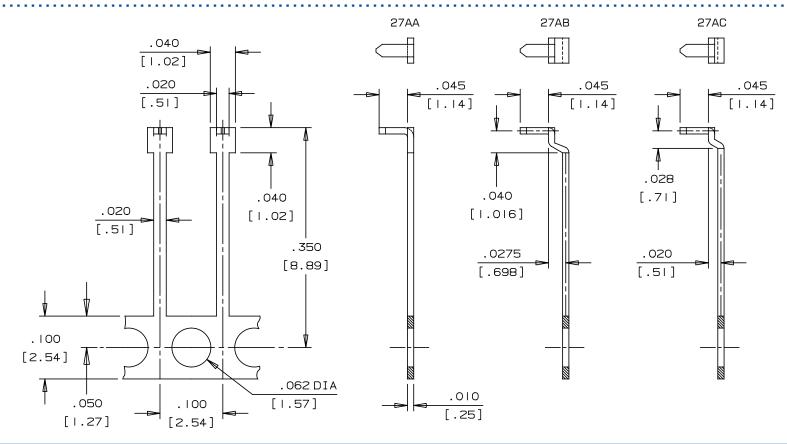
Through Hole Interconnects

	Dr	rawing N	0.	Pit	tch	Page
27AA	27AB	27AC		A = .100[2.54]		86
28AA				A = .100[2.54]		87
29AA	29AB			A = .100[2.54]		88
30AA				A = .100[2.54]		89
30BA				A = .100[2.54]		90





.100 [2.54] PITCH



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
F = THI	A = .100[2.54]	27AA 27AB 27AC	0 = No Solder	00 = None	See Chart on Page 11	O = No Stop S = Stop	O = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

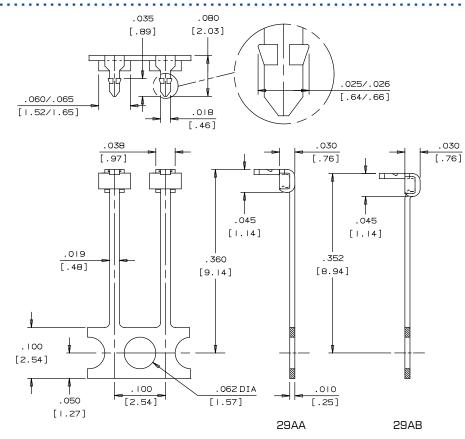
SELECT SPECIFIC OPTIONS TO DETERMINE ORDERING CODE:

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
F = THI	A = .100(2.54)	28AA	0 = No Solder	00 = None	See Chart on Page 11	O = No Stop S = Stop	0 = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	B = Winding (DB)
CODE:									

www.interplex.com/NAS

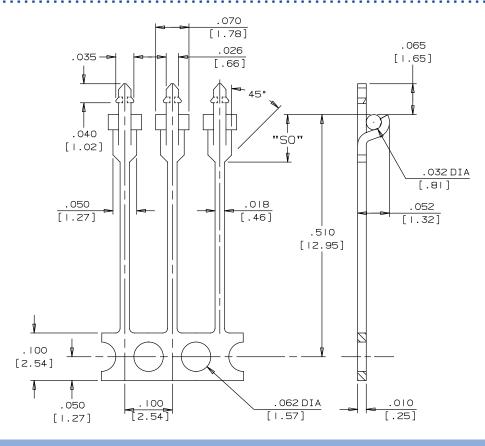
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.100 [2.54] PITCH



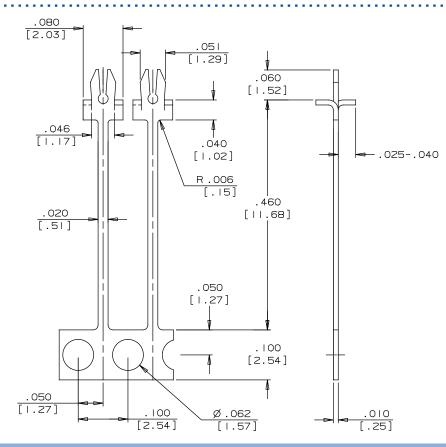
TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
F = THI	A = .100[2.54]	29AA 29AB	S = Bottom	OO = None	See Chart on Page 11	O = No Stop S = Stop	O = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

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TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
F = THI	A = .100[2.54]	30AA	S = Bottom	OO = None	See Chart on Page 11	O = No Stop S = Stop	L = .150[3.81] Y = .250[6.35]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

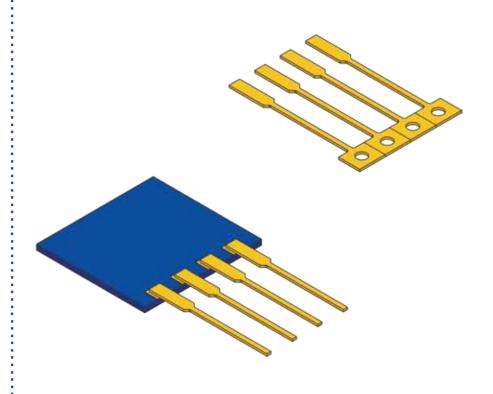
.100 [2.54] PITCH



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
F = THI	A = .100[2.54]	ЗОВА	0 = No Solder	OO = None	See Chart on Page 11	O = No Stop S = Stop	A = .040[1.00]	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

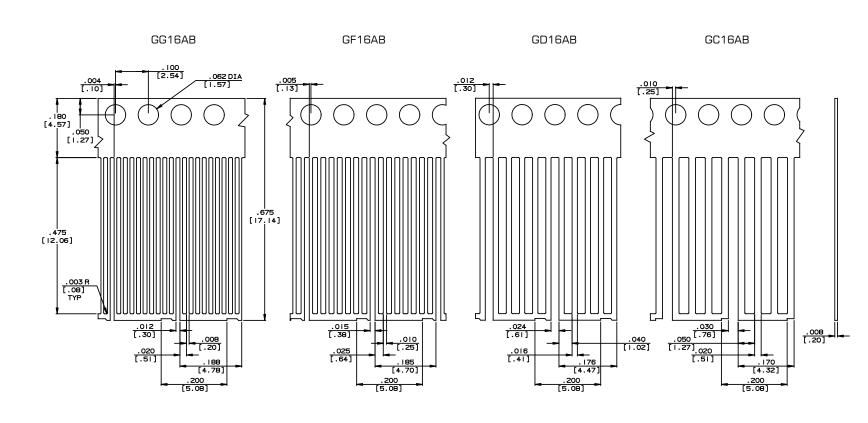
Special Interconnects

Drawir	ng No.		Pit	ch		Page
16AB		G = .020[0.51]	F = .025[0.635]	D = .040[1.02]	C = .050[1.27]	92
O4BA	04BF	A = .100[2.54]				93
04BB	04BE	A = .100[2.54]				94
07EA		C = .050[1.27]				95
13EA		C = .050[1.27]				96
24EA		B = .075[1.905]				97
25EA		A = .100[2.54]				98
26EA		A = .100[2.54]				99
1457	1458	Q = .125[3.175]				100

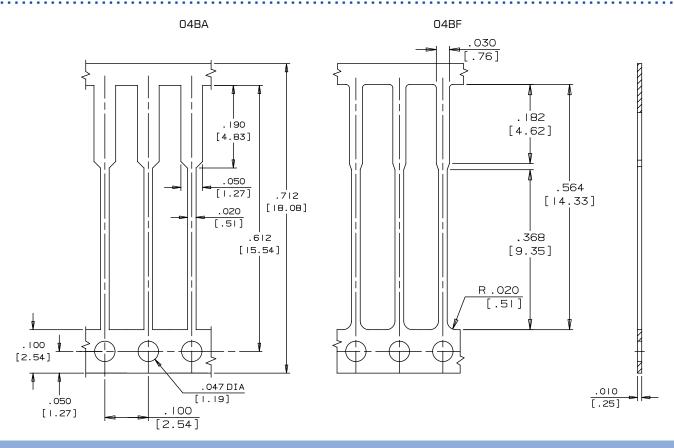




.020 [0.51] / .025 [0.635] / .040 [1.02] / .050 [1.27] Pitch



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
G = SPECIAL	G = .020 [0.51] F = .025 [0.635] D = .040 [1.02] C = .050 [1.27]	16AB	0 = No Solder	00 = None	See Chart on Page 11	O = No Stop S = Stop	0 = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

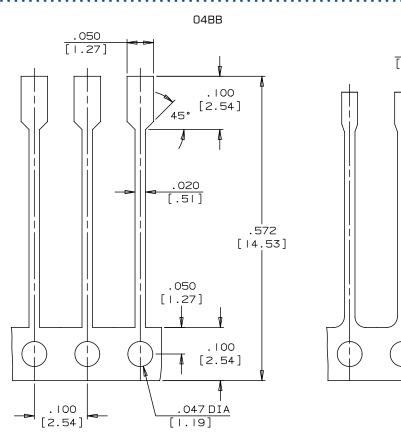


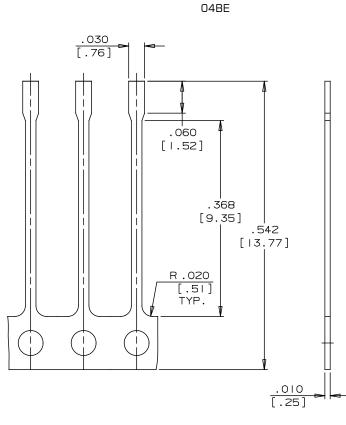
TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
G = SPECIAL	A = .100[2.54]	04BA 04BF	0 = No Solder	OO = None	See Chart on Page 11	O = No Stop S = Stop	0 = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

94

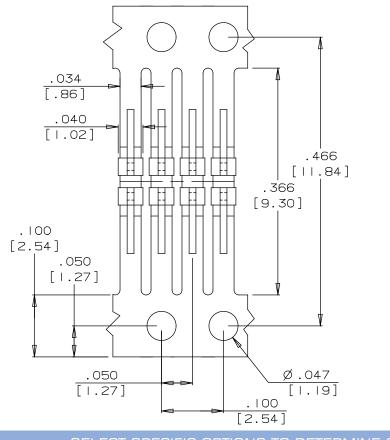


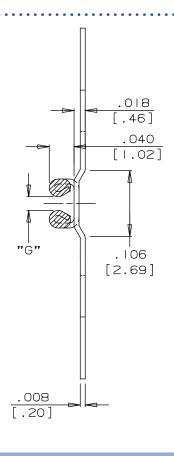
.100 [2.54] PITCH





O4BE on Page 11 S = Stop Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre-	TYPE	YPE PITCH (P)	DRWG. SOLDER NO. LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	G = SPEC	PECIAL A = .100(2.54)		OO = None			O = None	Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze	D = Winding (DD)





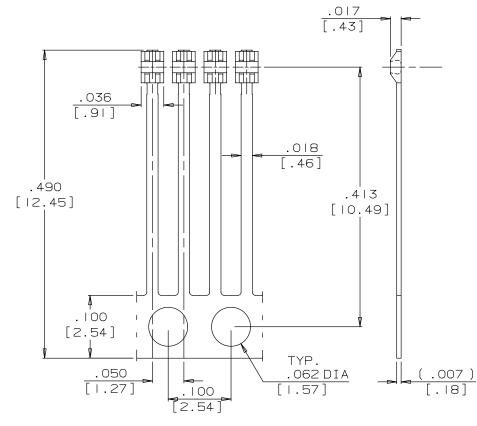
SELECT SPECIFIC OPTIONS TO DETERMINE ORDERING CODE:

TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
G = SPECIAL	C = .050[1.27]	07EA	D = Double	22 = .022[0.559] 28 = .028[0.71]	See Chart on Page 11	O = No Stop S = Stop	O = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	D = Winding (DD)
CODE:									

CODE

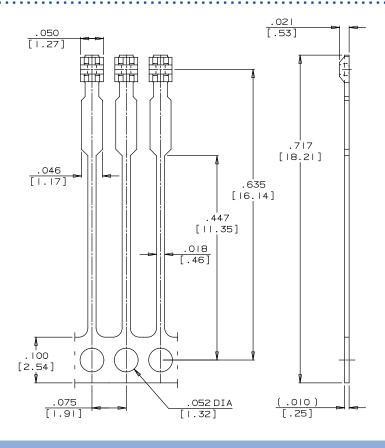
Interplex NAS

.050 [1.27] Pitch



TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
G = SPECIAL	C = .050 [1.27]	13EA	S = Bottom	OO = None	See Chart on Page 11	O = No Stop S = Stop	O = None	X = Beryllium Copper Pre-plated 100% Tin Finish I = Beryllium Copper Post- Plated 100% Tin Finish F = Beryllium Copper Post-Plated 60/40 Tin Lead Finish A = Beryllium Copper Pre-plated 60/40 Tin Lead Finish	D = WINDING (DD)
CODE:									

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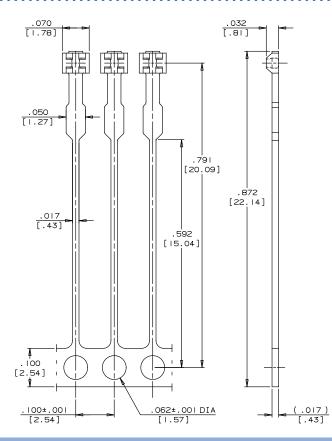


TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
G = SPECIAL	B = .075 [1.905]	24EA	S = Bottom	OO = None	See Chart on Page 11	O = No Stop S = Stop	X = See Drawing	E = Phosphor Bronze Preplated 100% Tin Finish K = Phosphor Bronze Postplated 100% Tin Finish H = Phosphor Bronze PostPlated Sn60/Pb40 C = Phosphor Bronze Preplated 60/40 Tin Lead Finish	D = WINDING (DD)
CODE:									

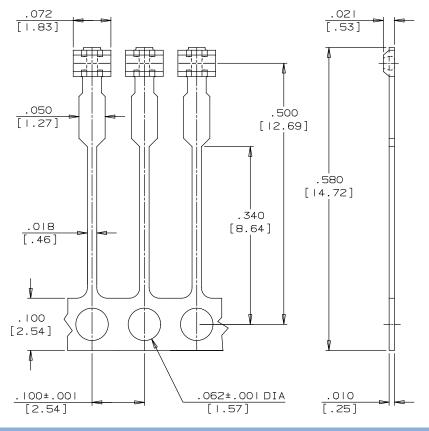
98

Interplex NAS

.100 [2.54] Pitch

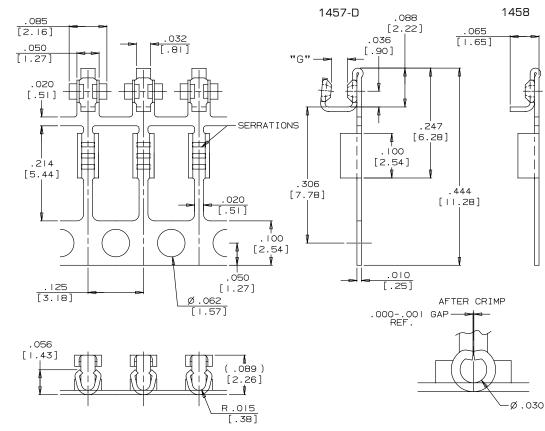


TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
G = SPECIAL	A = .100 [2.54]	25EA	S = Bottom	OO = None	See Chart on Page 11	O = No Stop S = Stop	x = See drawing	E = Phosphor Bronze Pre- plated 100% Tin Finish K = Phosphor Bronze Post- plated 100% Tin Finish H = Phosphor Bronze Post- Plated Sn60/Pb40 C = Phosphor Bronze Pre- plated 60/40 Tin Lead Finish	D = WINDING (DD)
CODE:									



TY	PE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
G = SF	PECIAL	A = .100 [2.54]	26EA	S = Bottom	00 = None	See Chart on Page 11	0 = No Stop S = Stop	x = See drawing	E = Phosphor Bronze Pre- plated 100% Tin Finish K = Phosphor Bronze Post- plated 100% Tin Finish H = Phosphor Bronze Post- Plated Sn60/Pb40 C = Phosphor Bronze Pre- plated 60/40 Tin Lead Finish	D = WINDING (DD)
CODE:										

. 125 [3. 175] PITCH



.056

	TYPE	PITCH (P)	DRWG. NO.	SOLDER LOCATION	GAP (G)	SOLDER TYPE	SOLDER STOP	STAND OFF (SO)	MATERIAL/ PLATING	STANDARD ORIENTATION
	G = SPECIAL	Q = .125 (3.175)	1457 1458	D = Double S =Single	00 = None 36 = .036[0.914]	See Chart on Page 11	O = No Stop S = Stop	O = None	E = Phosphor Bronze Pre- Plated 100% Sn K = Phosphor Bronze Post-Plated 100% Sn C = Phosphor Bronze Pre- Plated Sn60/Pb40 H = Phosphor Bronze Post-Plated Sn60/Pb40	F = Winding (SB)
H	CODE:									



GLOBAL LEADERSHIP IN INTERCONNECT SOLUTIONS



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